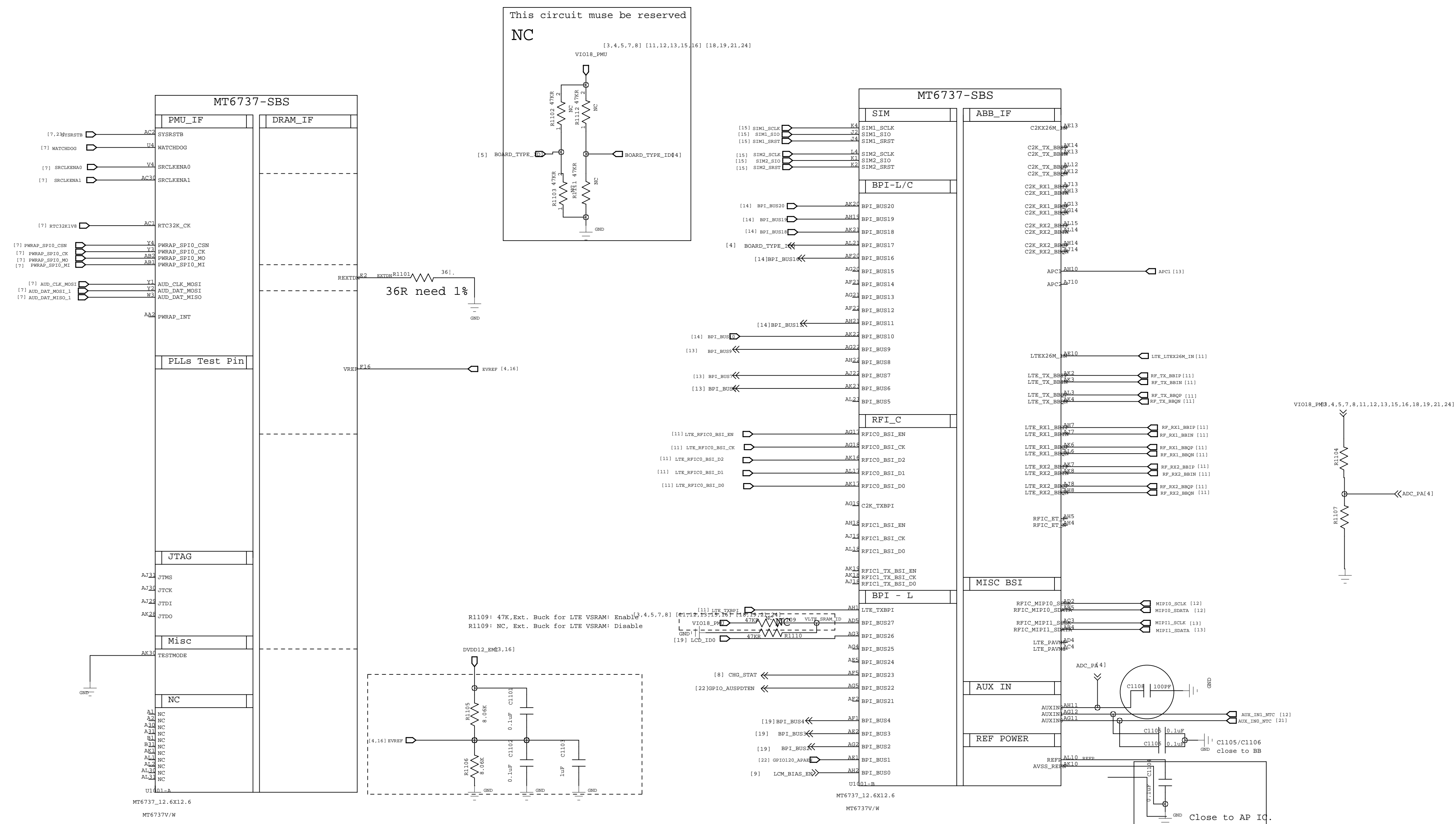
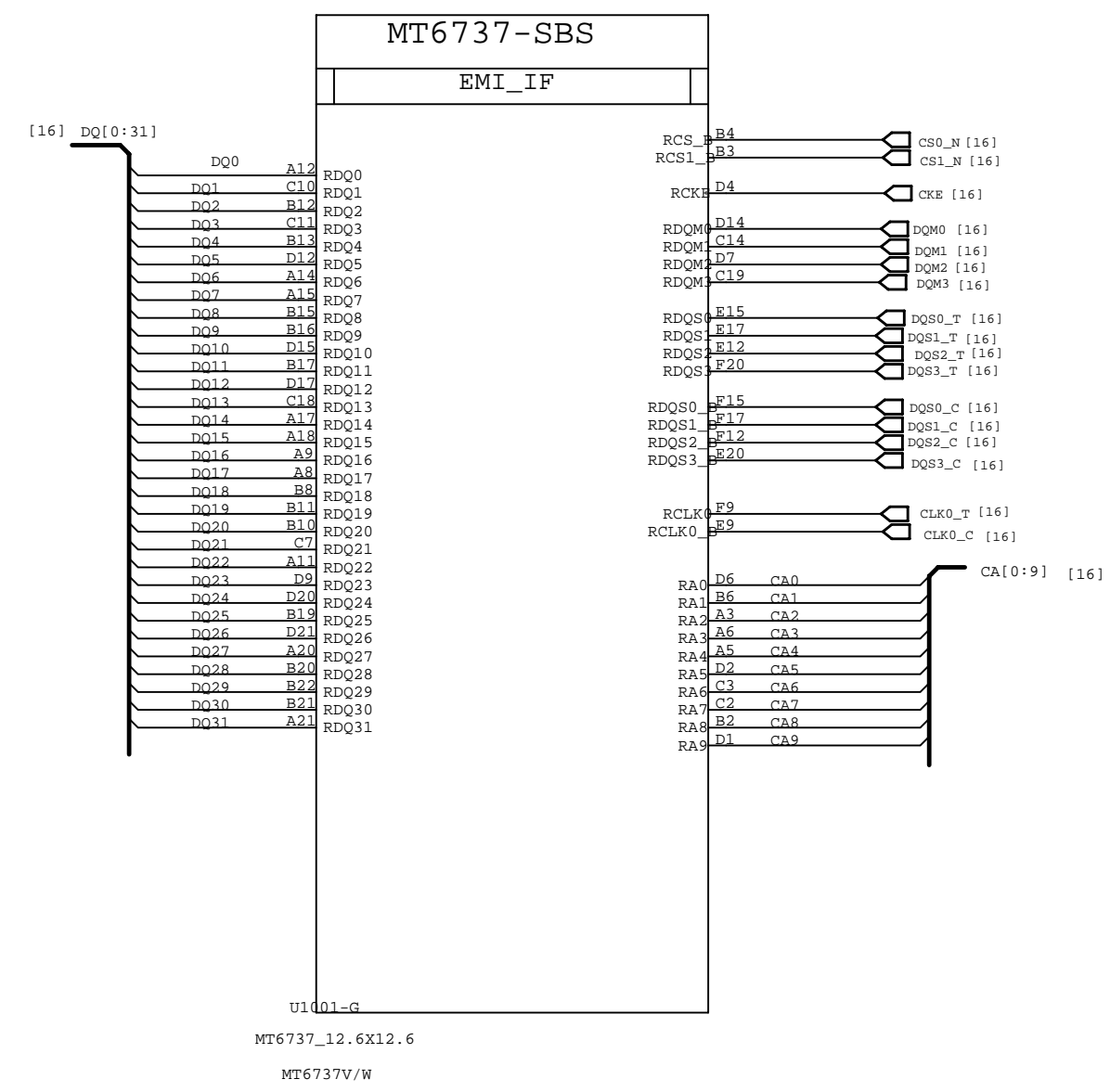
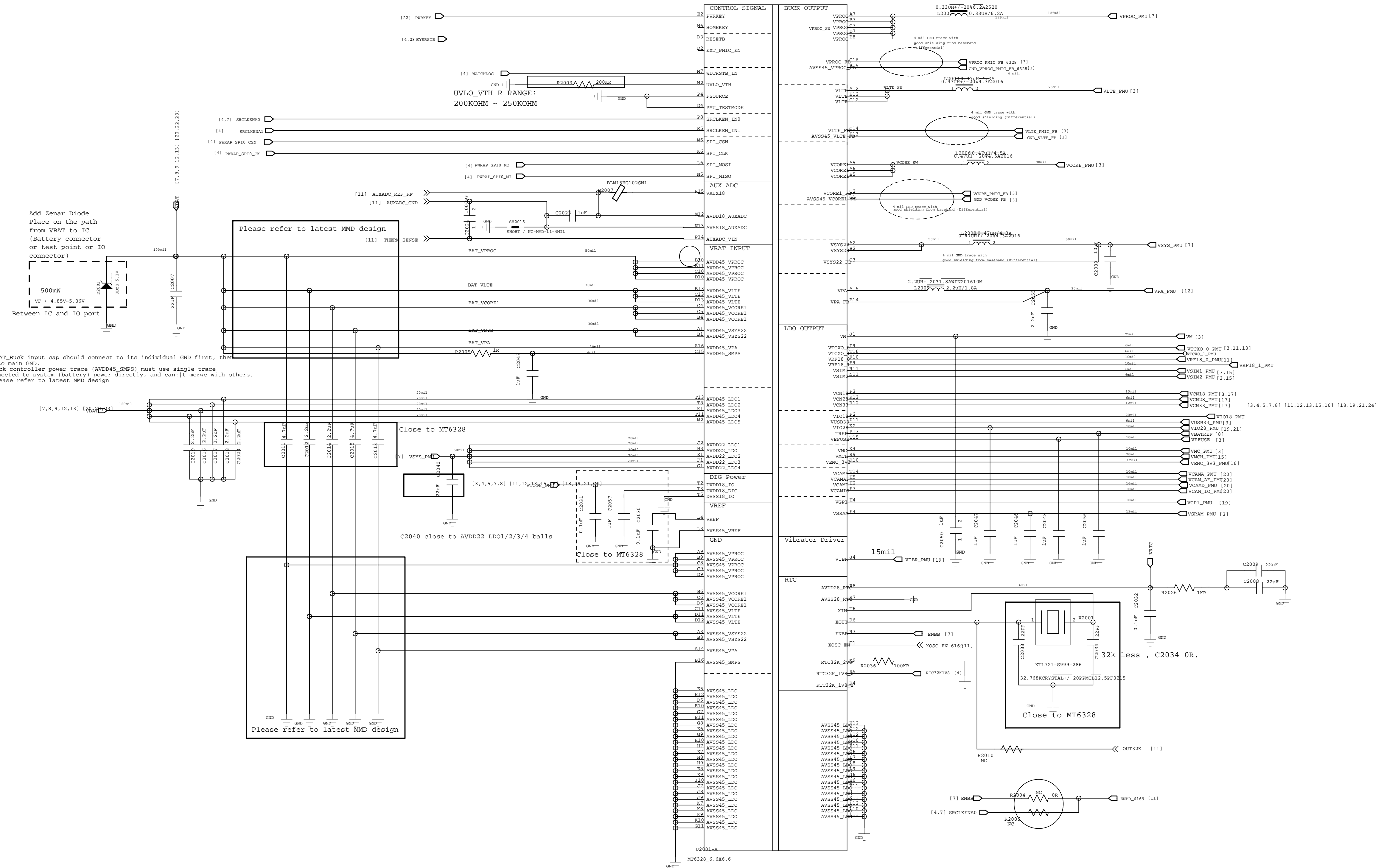


I2C	Function	I2C Spec.	Budget Timing	I2C Slave Address (7-bit mode)
I2C-0	Rear Camera - 13M	400 Kbps	Yes.	Rear camera (IMX135) I2C address: 0X10 (Write:0x20, Read:0x21) AF driver (DW9714A) I2C address: 0x0C (Write:0x18 , Read:0x19)
	Front Camera	400 Kbps	Yes.	Front camera (GC2355) I2C address: 0x3C (Write:0x78, Read:0x79)
I2C-1	CTP	400 Kbps	Yes.	GT1151 / CTP I2C address: 0X5D (Write:0xBA, Read:0xBB) or 0x14 (Write:0x28, Read:0x29)
I2C-2	M Sensor	2.5 Mbps		AK09911 / M-Sensor I2C Address: 0x0D (Write:0x1A, Read:0x1B)
	Gyro Sensor	400 Kbps	Yes.	ITG1010 / Gyro I2C Address: 0x68 (Write:0xD0, Read:0xD1)
	Accelerometer	400 Kbps		MC3410 / Accelerometer I2C address: 0x4C (Write:0x98, Read:0x99)
	RGB / PS Sensor	400 Kbps		CM36652 / RGB+PS I2C address: 0X60 (Write:0xC0, Read:0xC1)
	NFC	1.2 Mbps	Yes.	MT6605 / NFC I2C address: 0X28 (Write:0x50, Read:0x51)
	Flashlight Driver	400 Kbps		LM3642 / Flashlight Driver I2C address: 0X63 (Write:0xC6, Read:0xC7)
I2C-3				

Note : I2C Spec. : Standard mode (100 kbps) and Fast mode (400 kbps), Fast mode Plus (1 Mbps) and High-speed mode (3.4 Mbps)







Add Zener Diode
Place on the path
from VBAT to IC
(Battery connector
or test point or IO
connector)

500mA
VP : 4.85V-5.36V

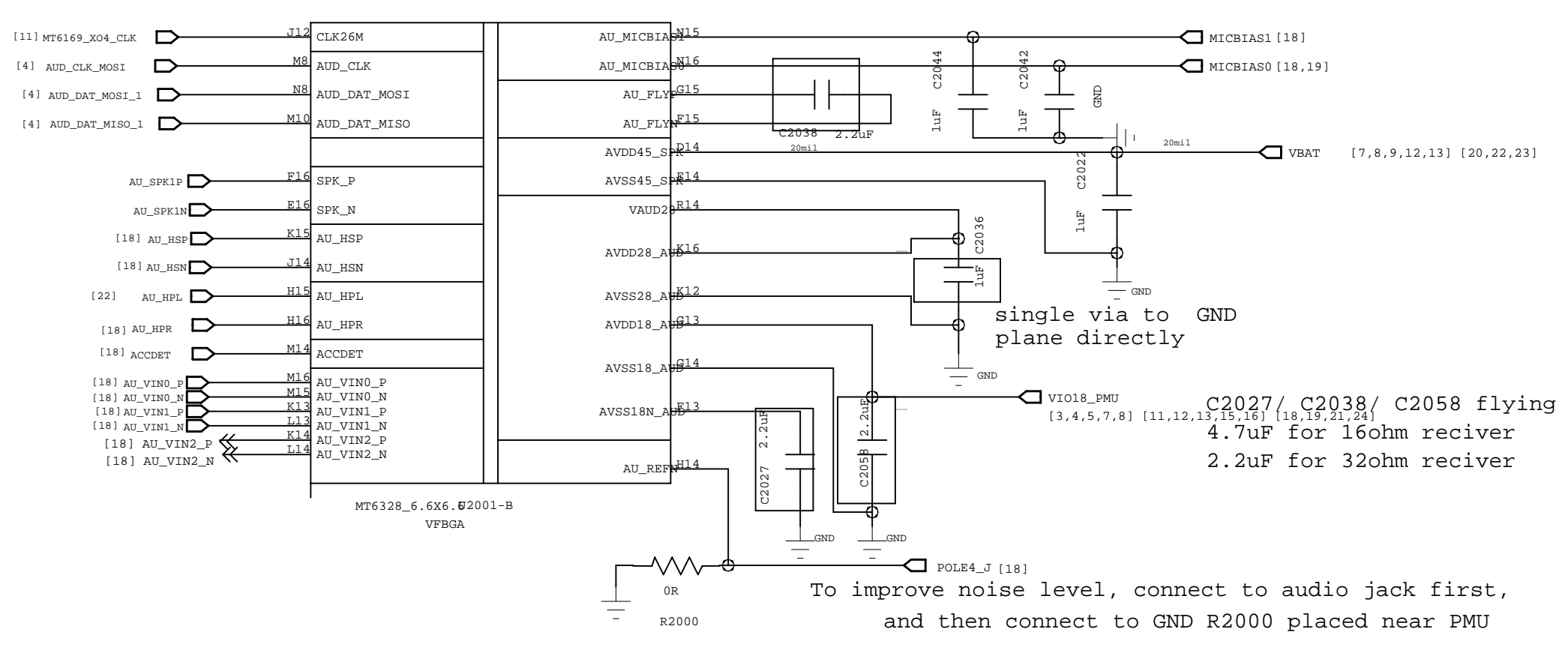
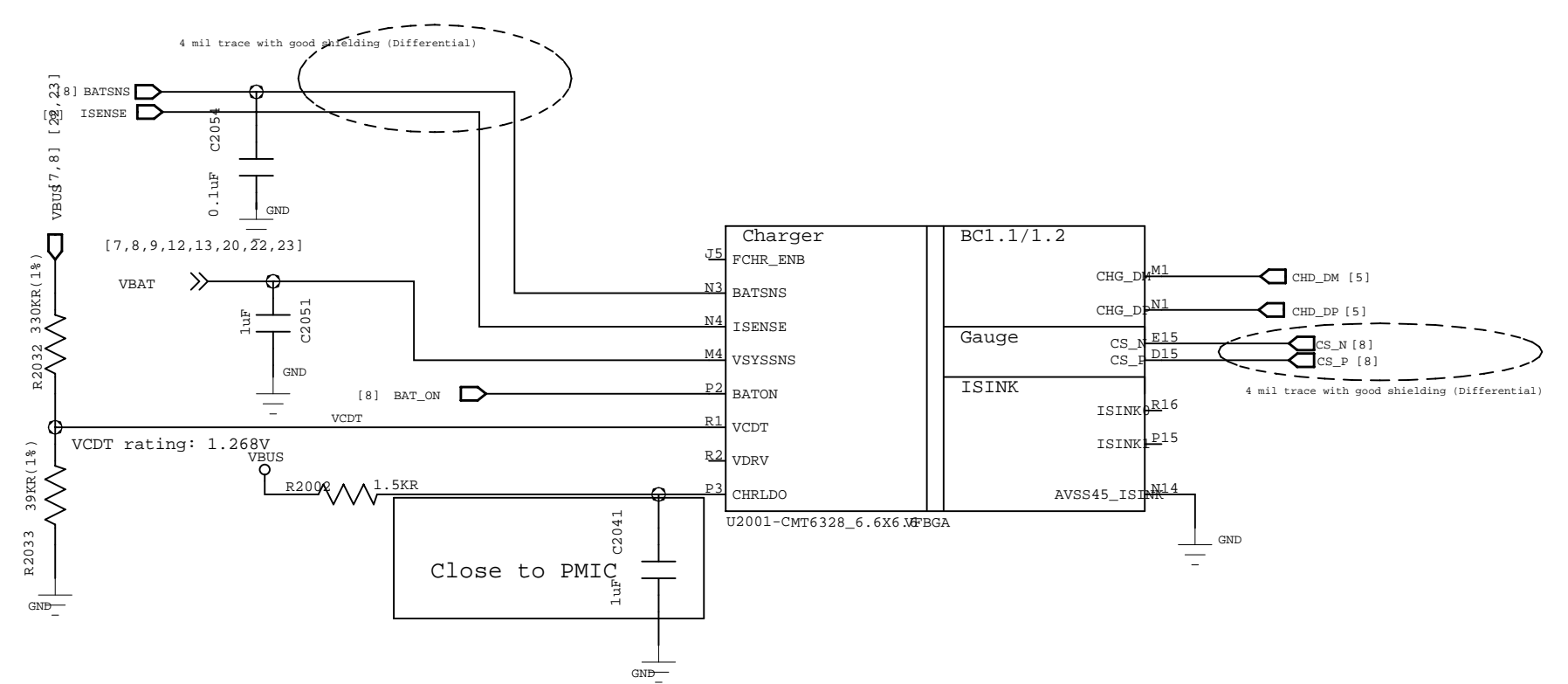
- VBAT_Buck input cap should connect to its individual GND first, then go to main GND.
- Buck controller power trace (AVDD45_SMP5) must use single trace connected to system (battery) power directly, and can't merge with others.
- Please refer to latest MMD design

Please refer to latest MMD design

C2040 close to AVDD22_LD01/2/3/4 balls

Please refer to latest MMD design

Audio

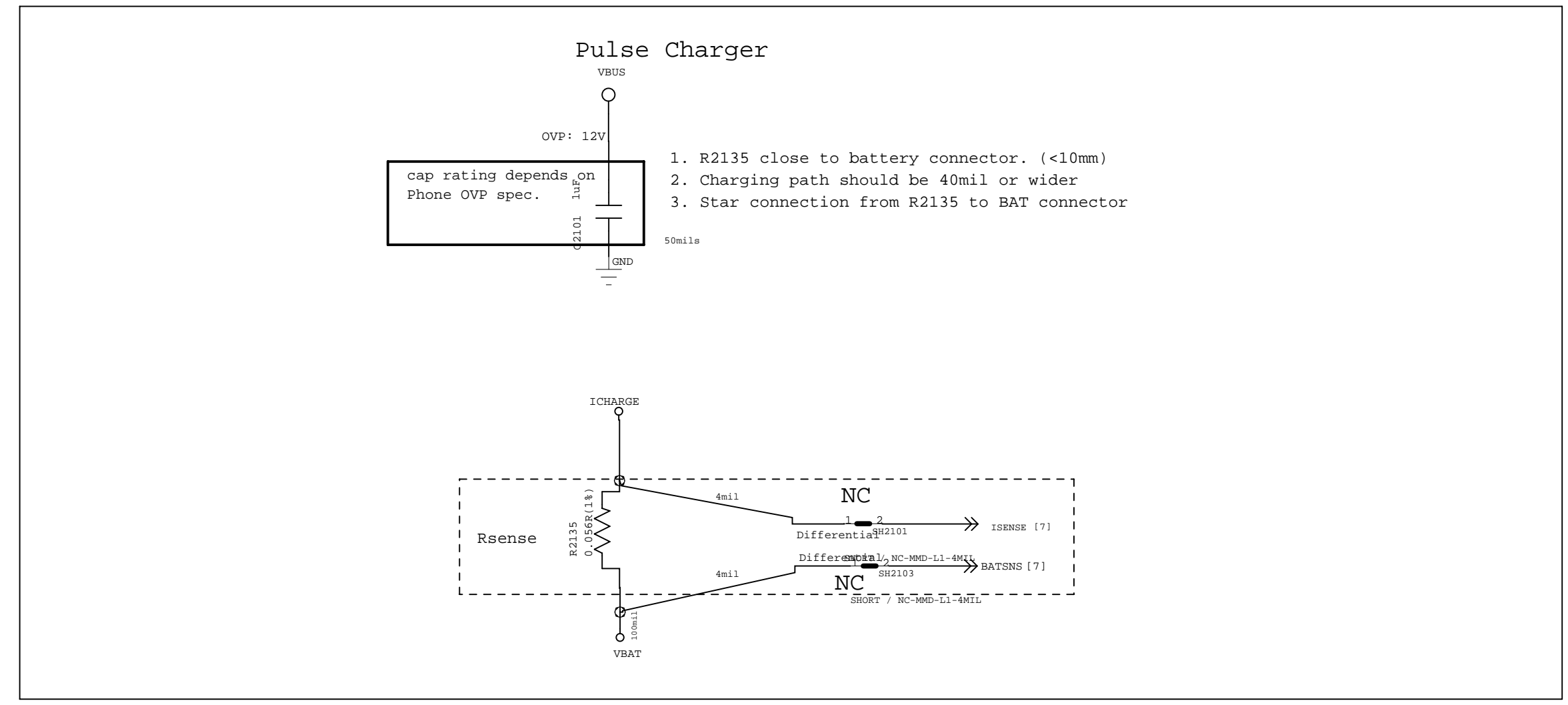
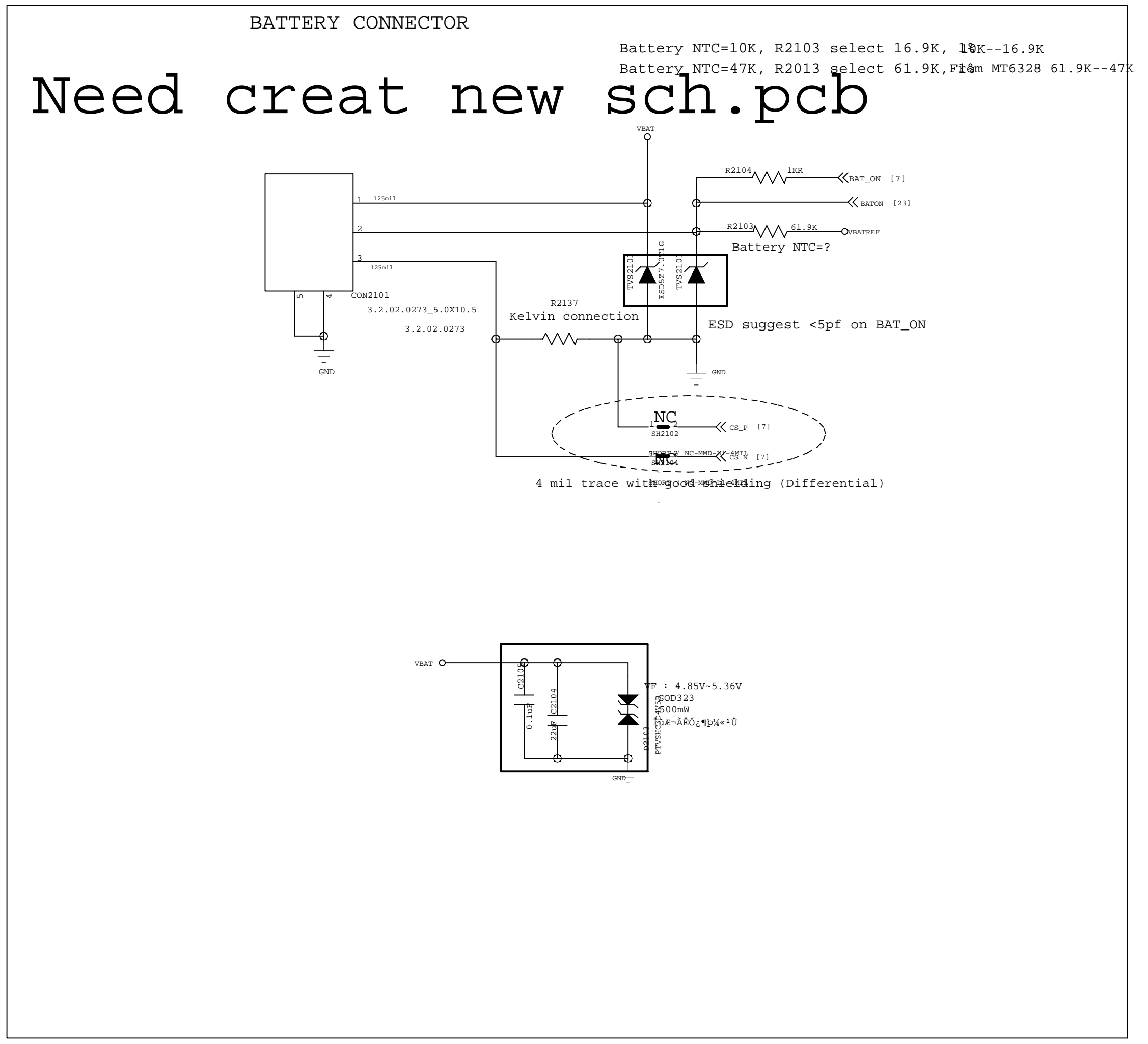


single via to GND plane directly

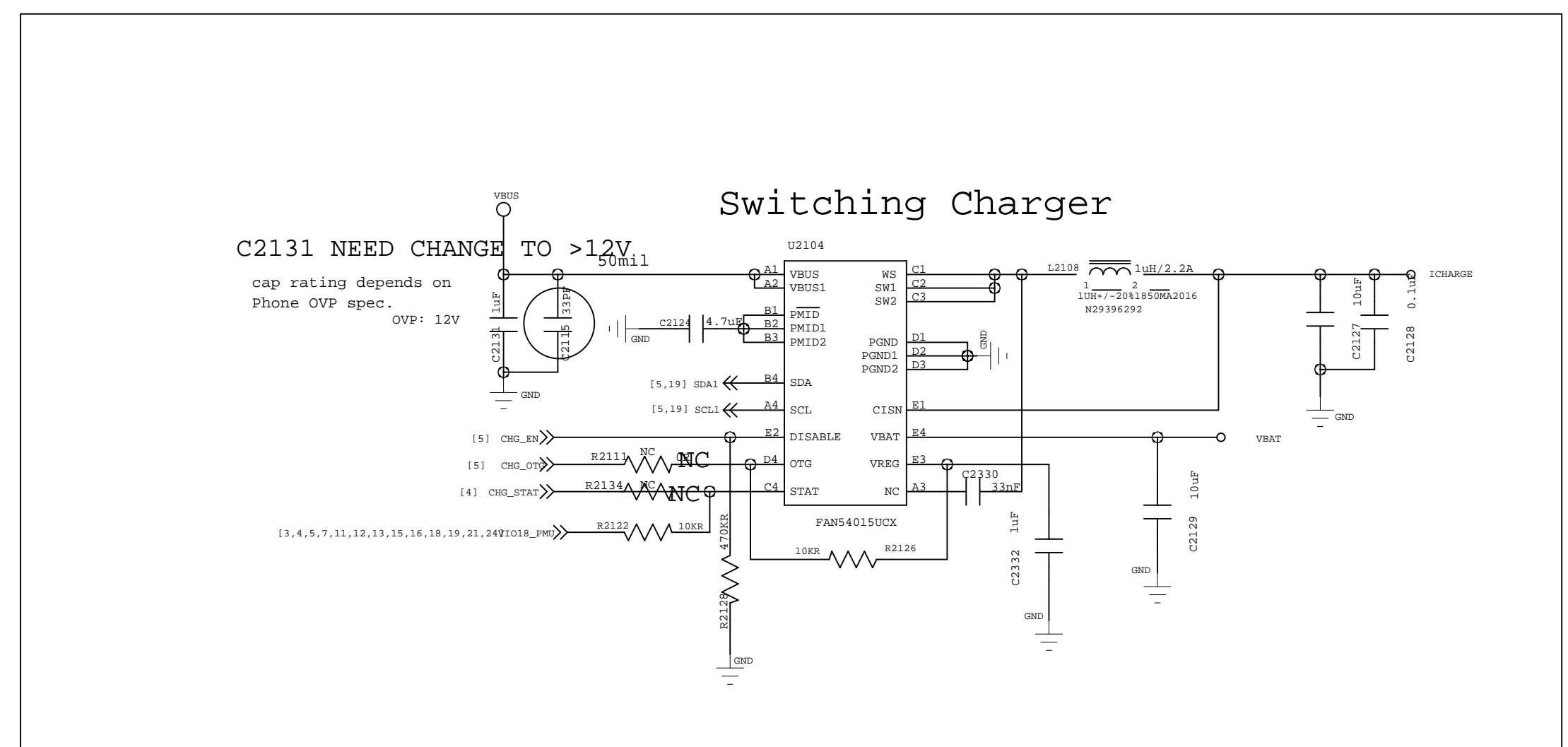
C2027/ C2038/ C2058 flying cap & holding cap :
4.7uF for 16ohm receiver
2.2uF for 32ohm receiver

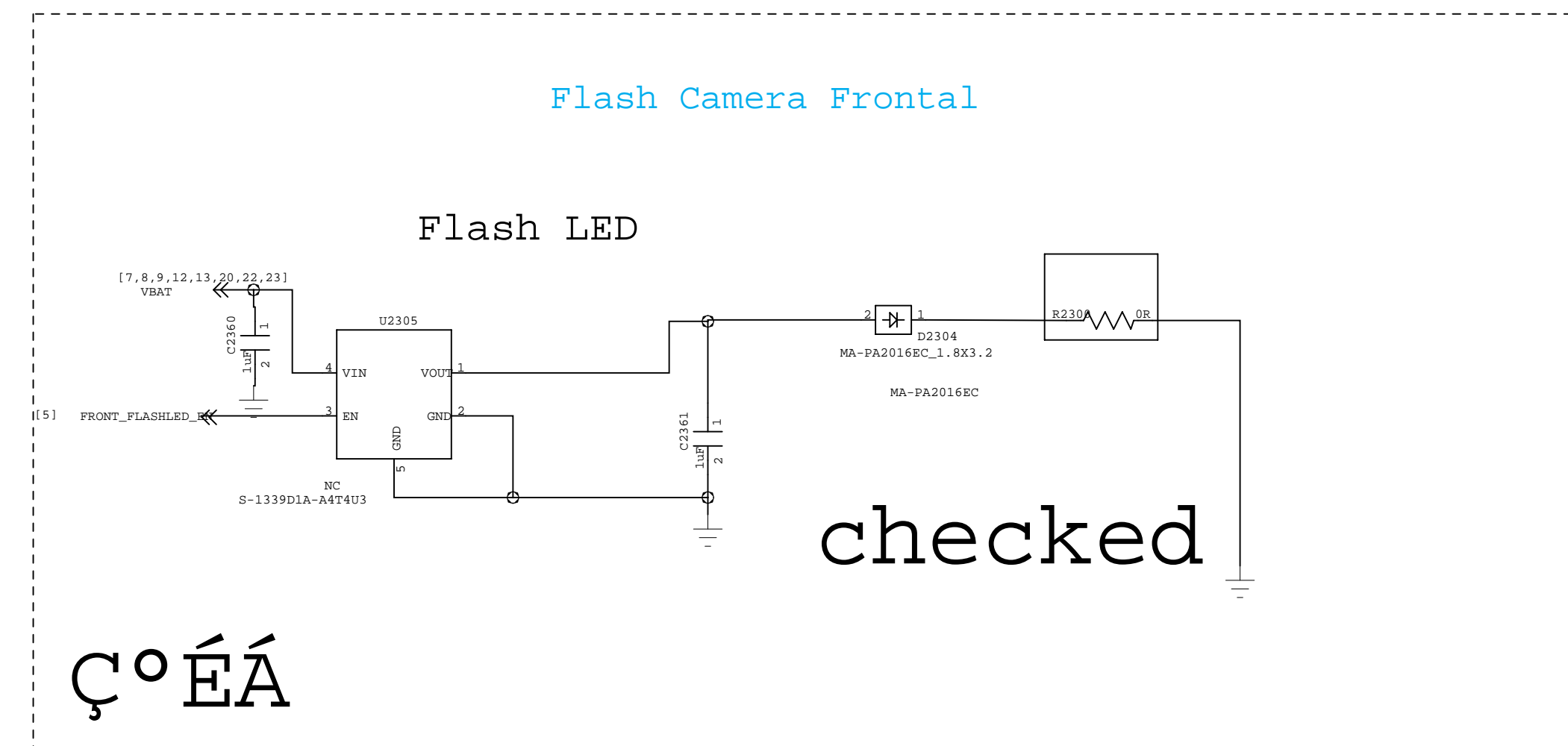
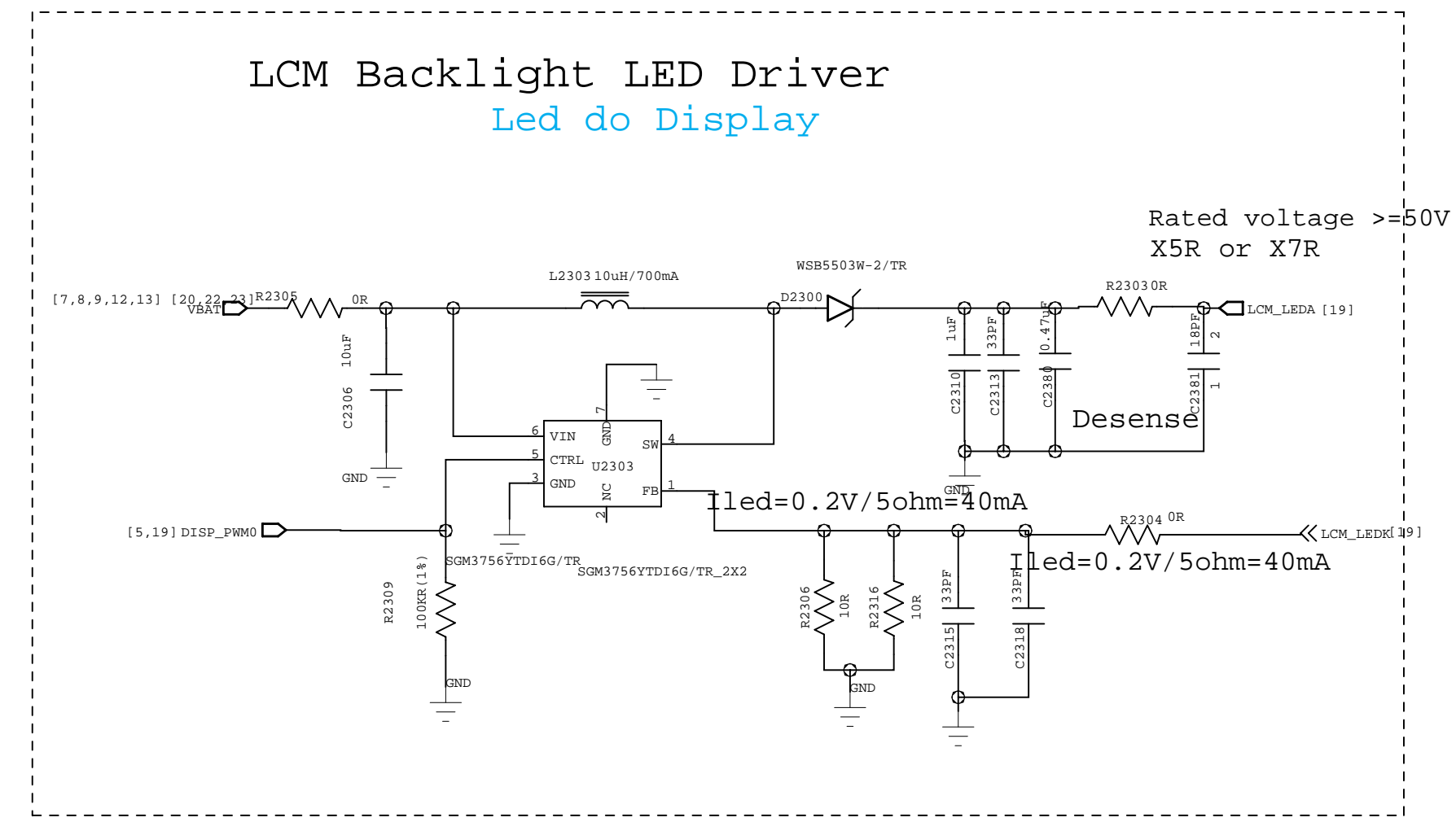
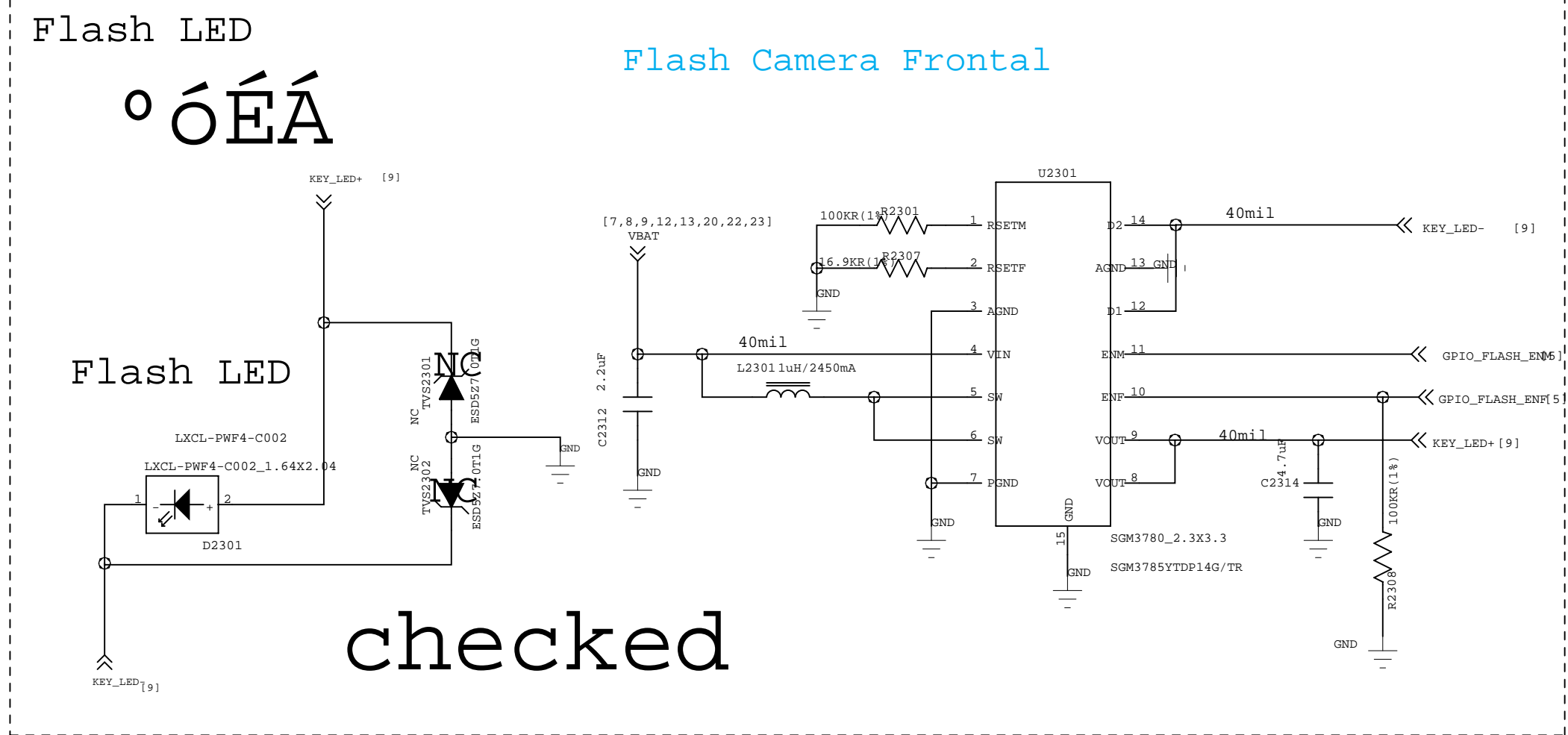
To improve noise level, connect to audio jack first, and then connect to GND R2000 placed near PMU

Title		20_POWER_MT6328
Size D		Yude Confidential
Data	Sep 14, 2016	Sheet 20 of 99



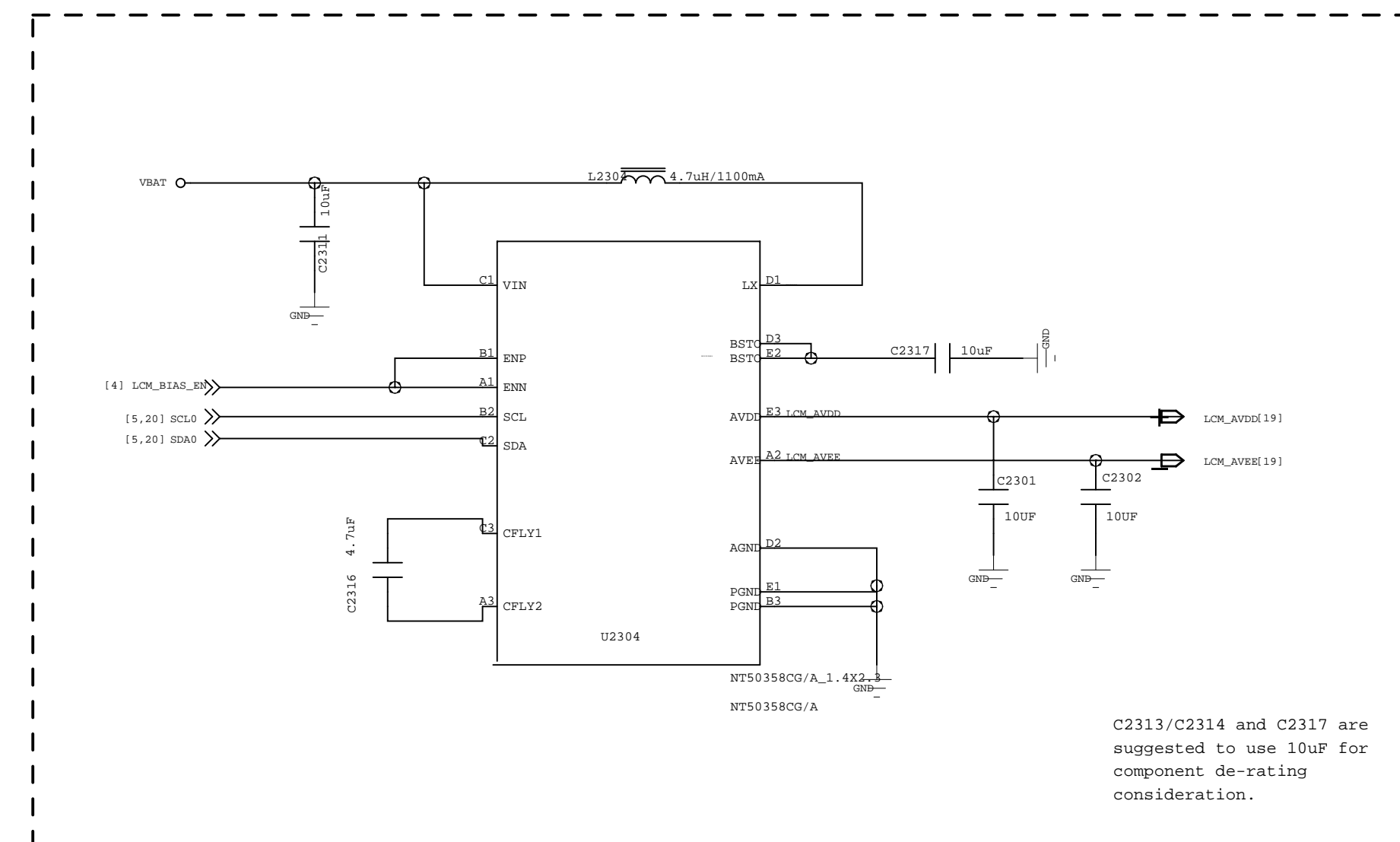
⌘ⓂⓈ±ℓ»αÉ¾³ ý×ϕòâ∇BATÍøÂç





LCM Gate Drive

LCM Gate Driver I2C address: 0X3E (Write:0x7C, Read:0x7D)



have checked

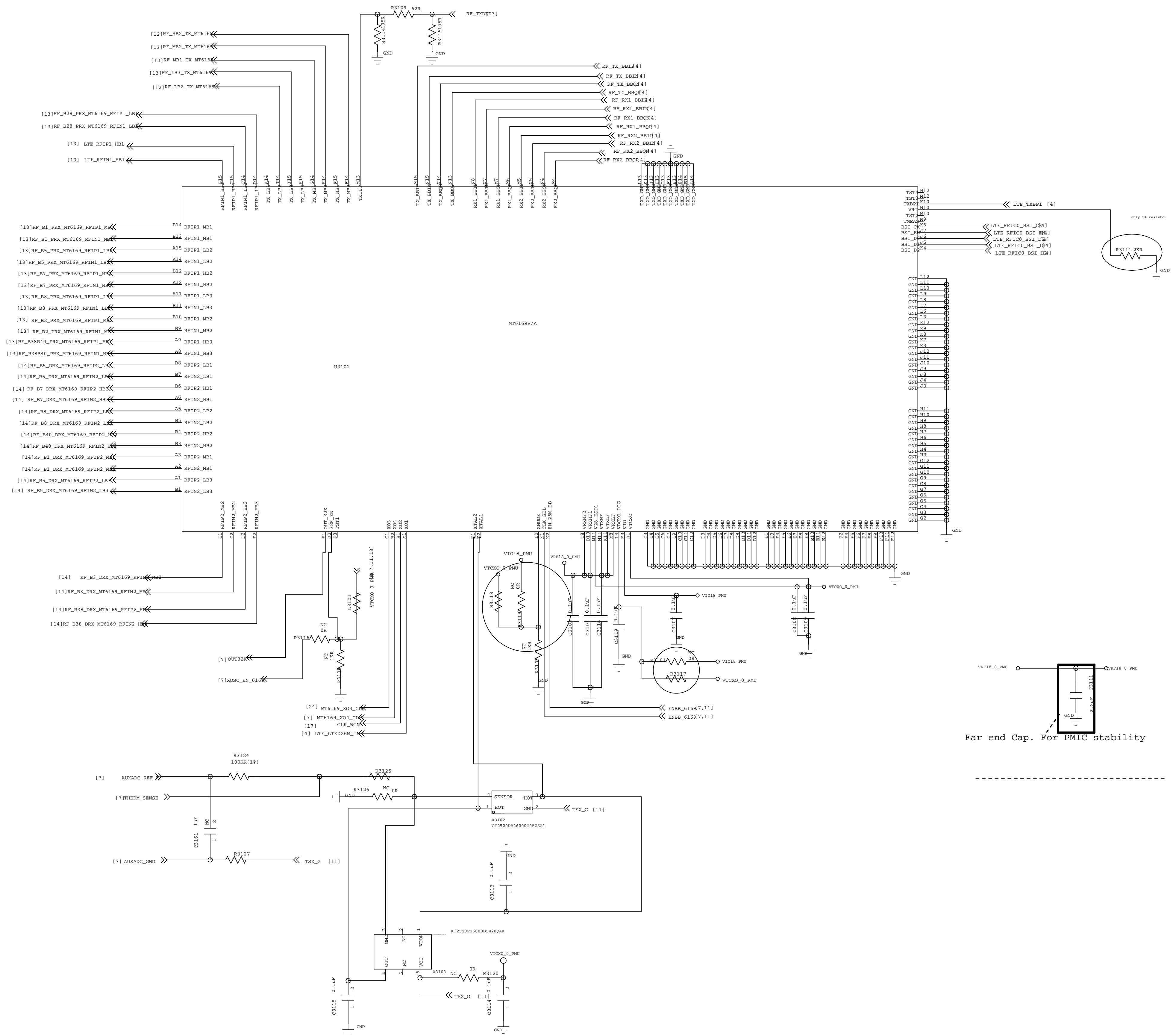
Title	23_POWER_FLASH_LCM BL	
Size D	Yude Confidential	
Data	Sep 14, 2016	Sheet 11 of 99

External Buck for DRAM

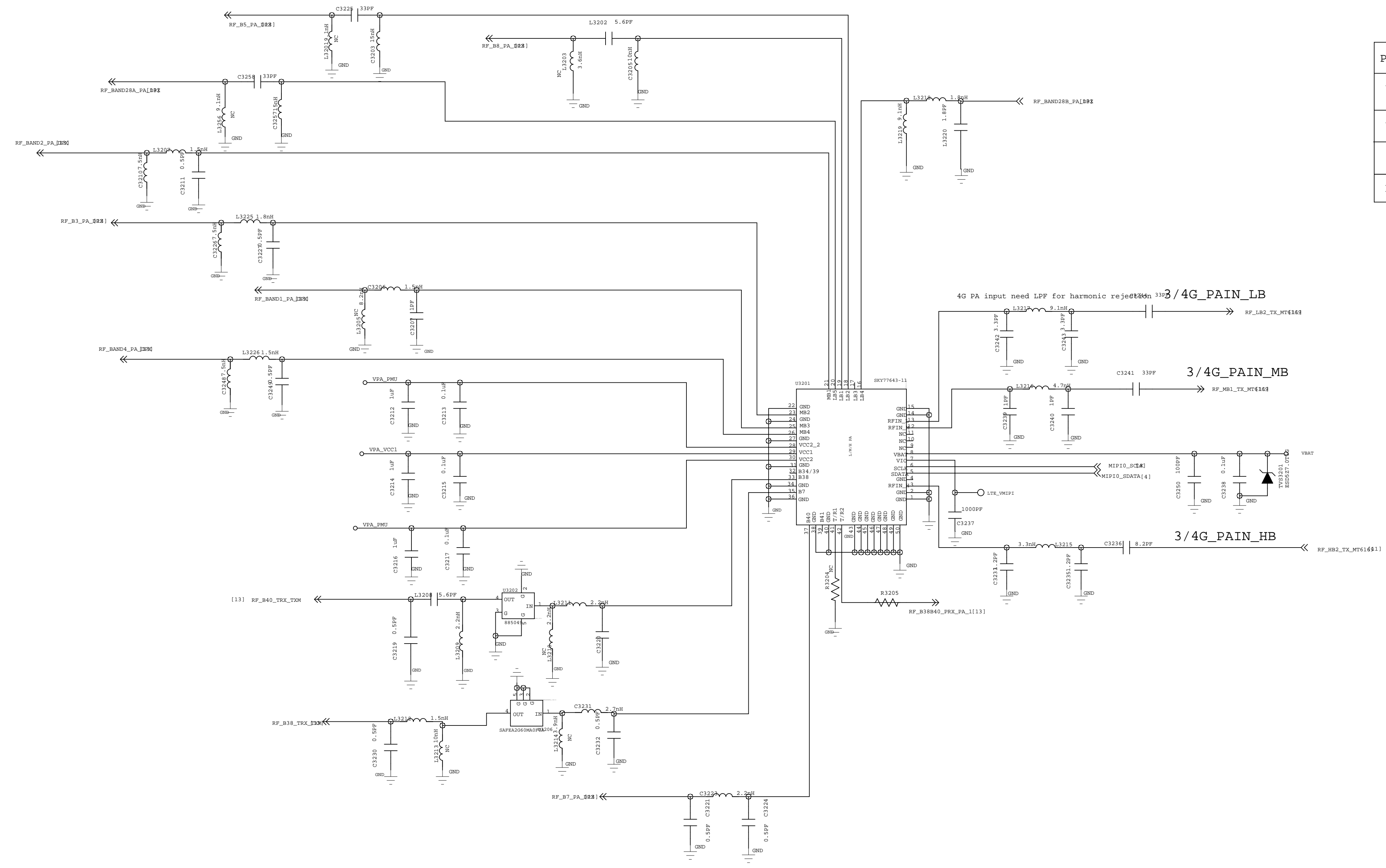
If using external buck for DRAM application, please refer to "MT6735_53 DRAM External Buck Design Notice":
1. Please add one more 1uF capacitor on PMIC VM output side (Must)
2. Please turn off Fast Transient Function of PMIC VM LDO (Must)

Title		24_NONE	
Size D		Yude Confidential	
Data	Sep 14, 2016	Sheet	11 of 99

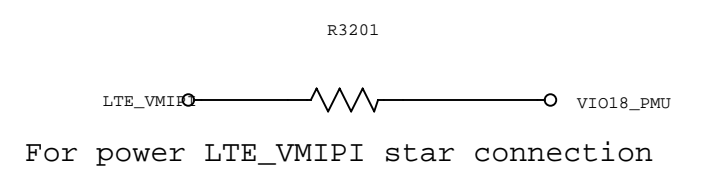
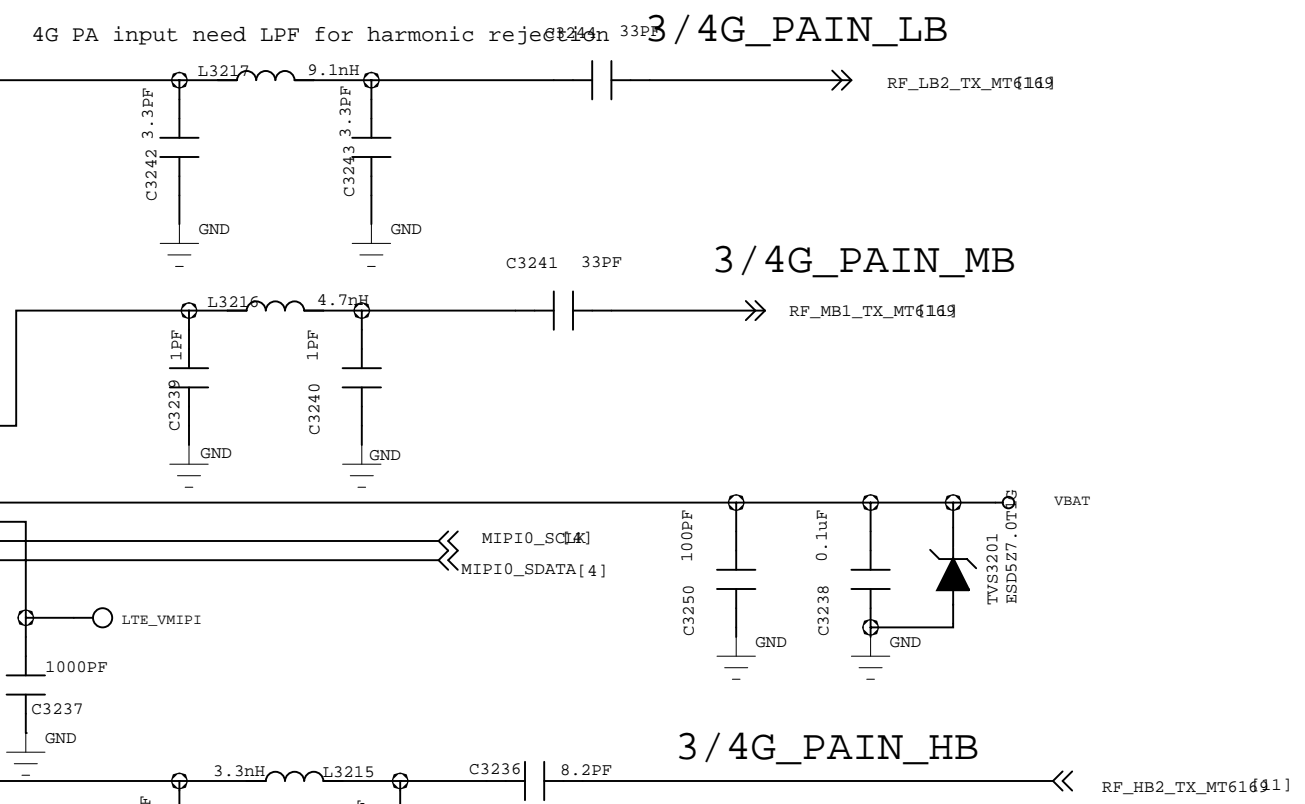
Power trace	PCB line width	MAX current
VRF18_0_PMU	0.4mm	
VIO18_PMU	0.35mm	
VTCXO_0_PMU	0.2mm	



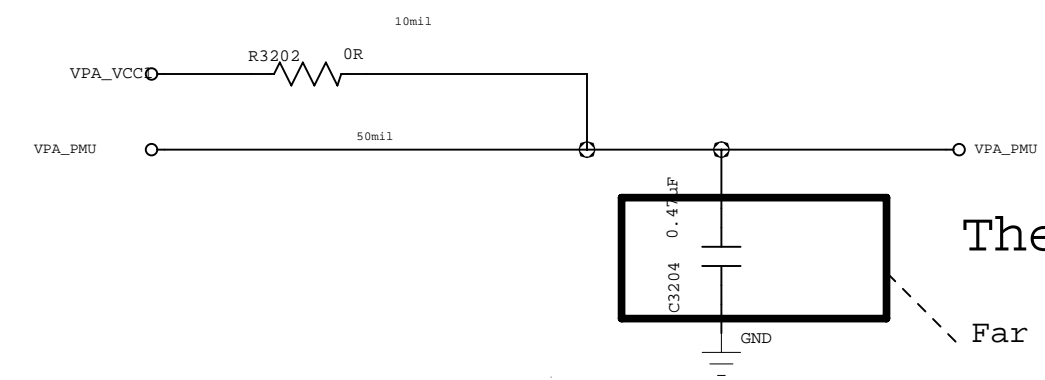
Far end Cap. For PMIC stability



Power trace	PCB line width	MAX current
VPA_PMU	1.1mm	
VPA_VCC1	0.5mm	
VBAT	0.15mm	
LTE_VMIPI	0.15mm	



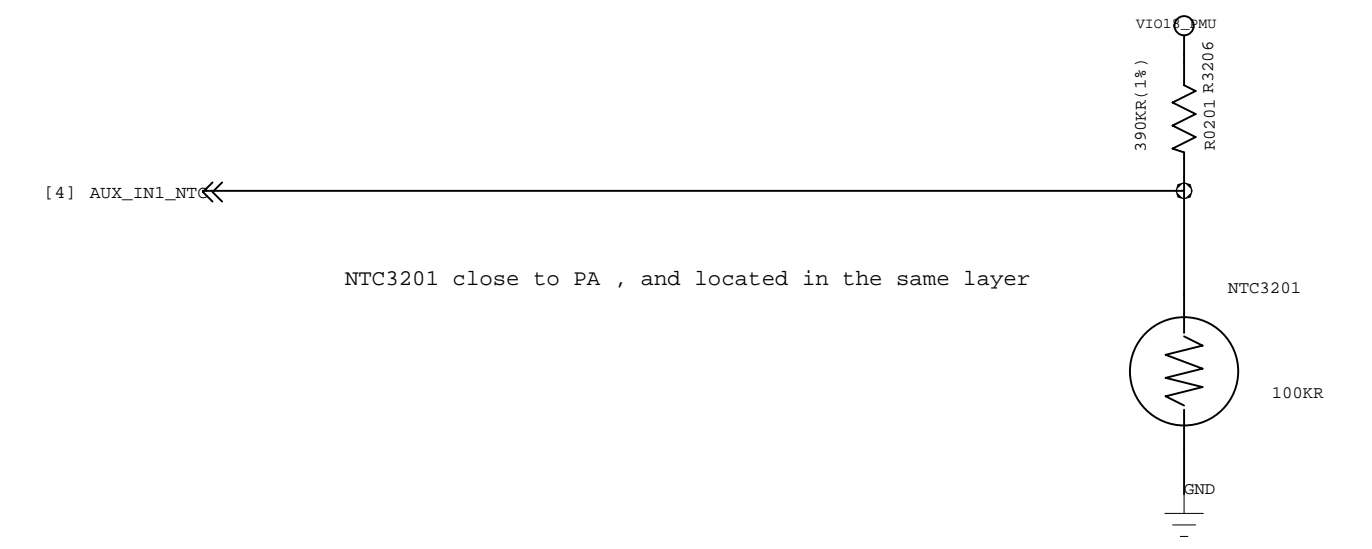
VPA_VCC1 and VPA PMU need to be connected after Cap



Thermistor / To sense board level temperature

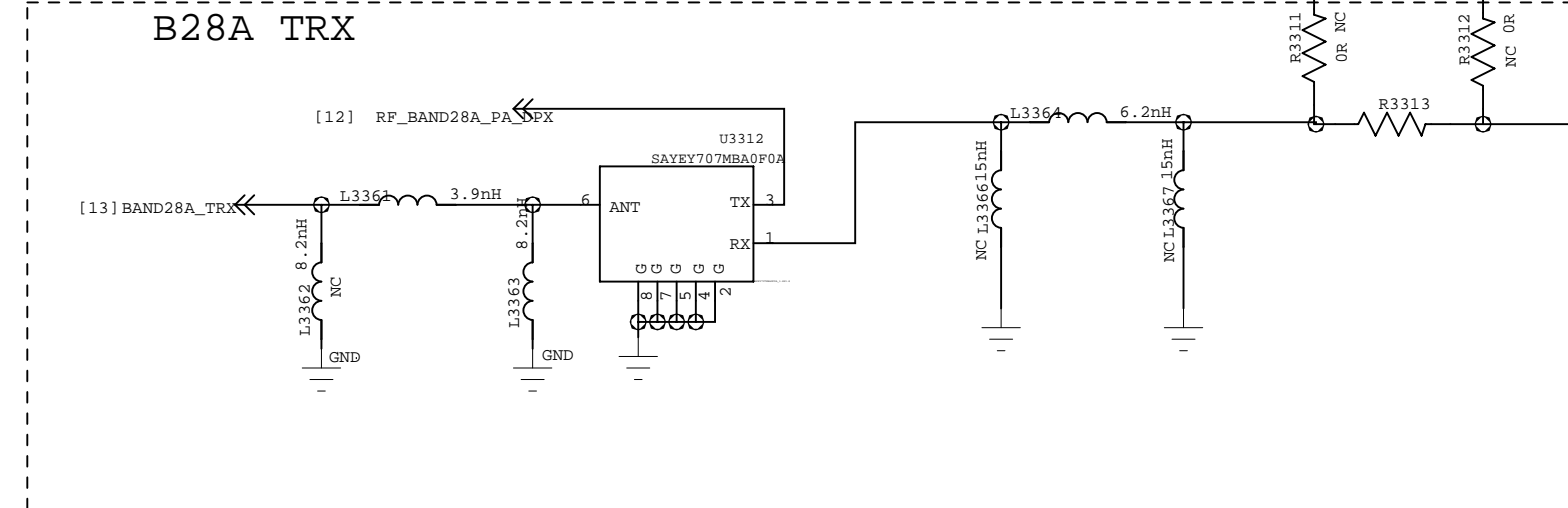
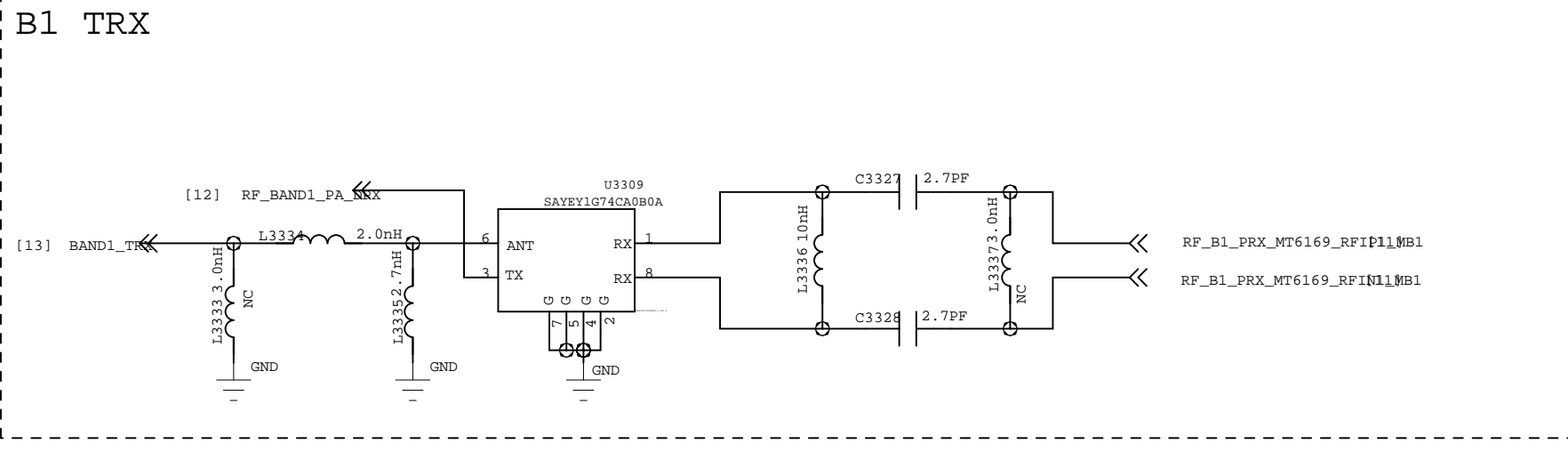
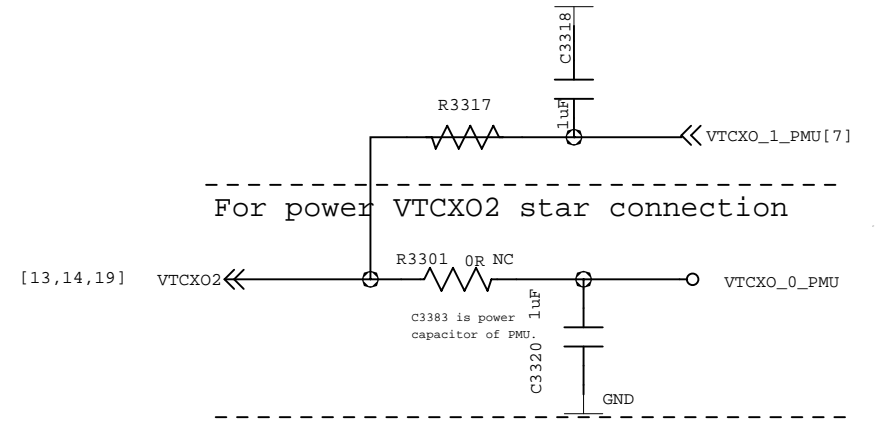
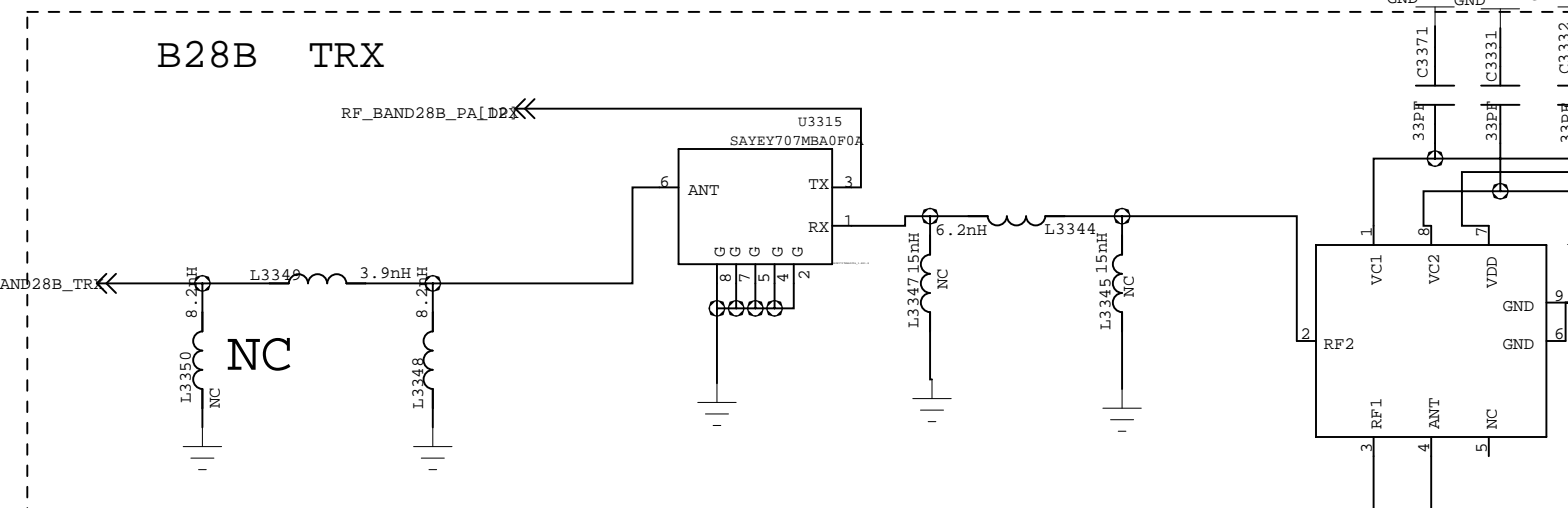
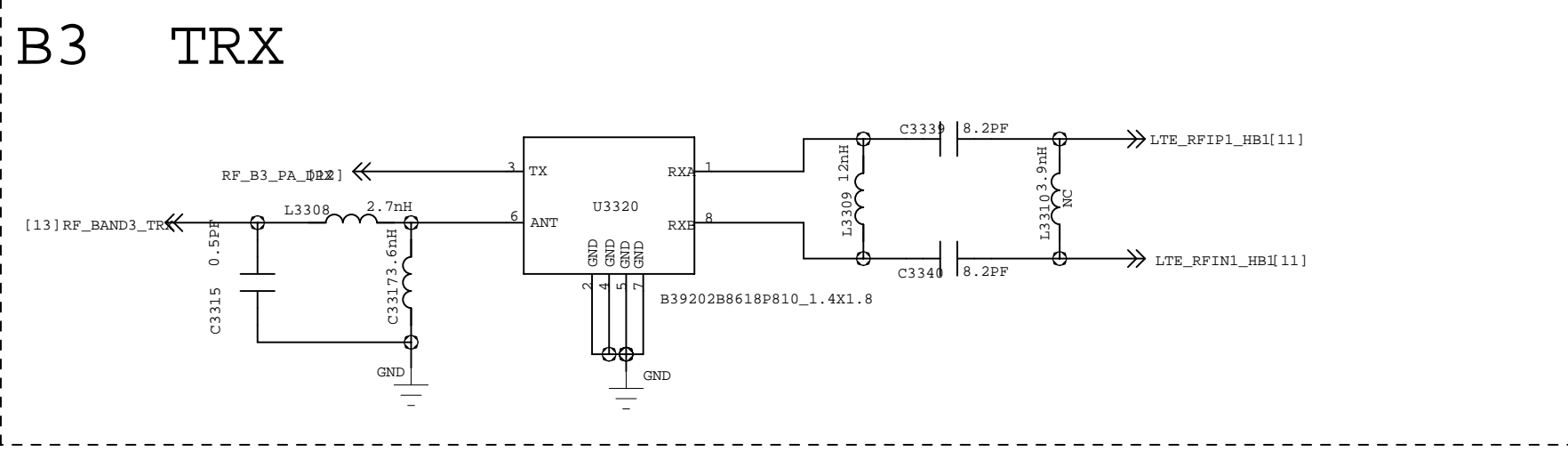
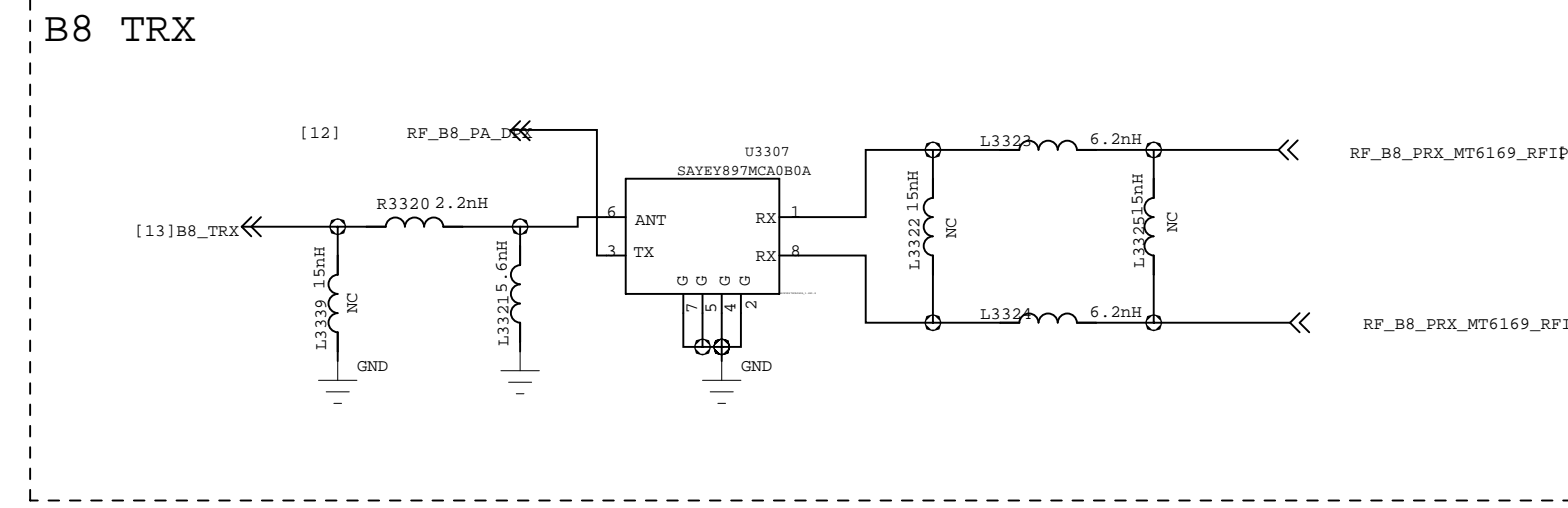
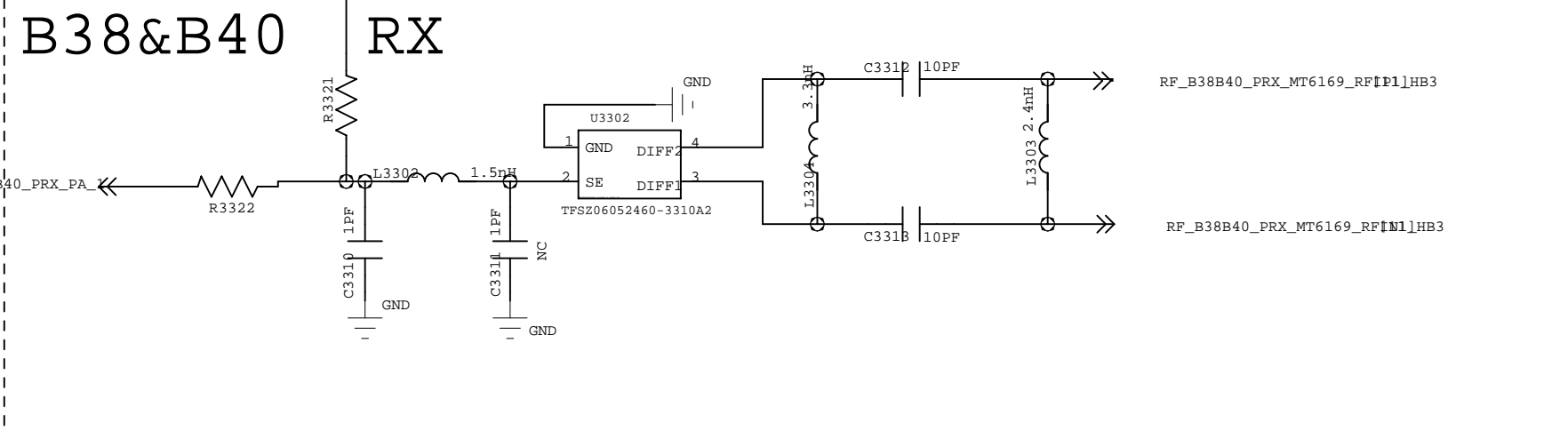
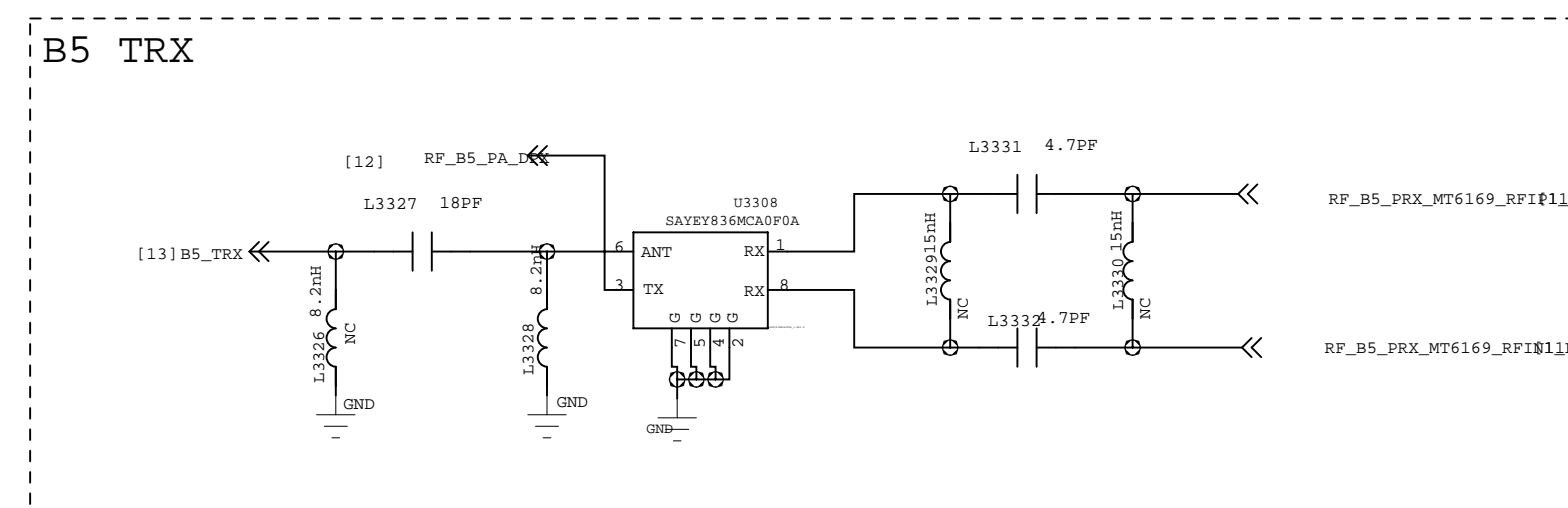
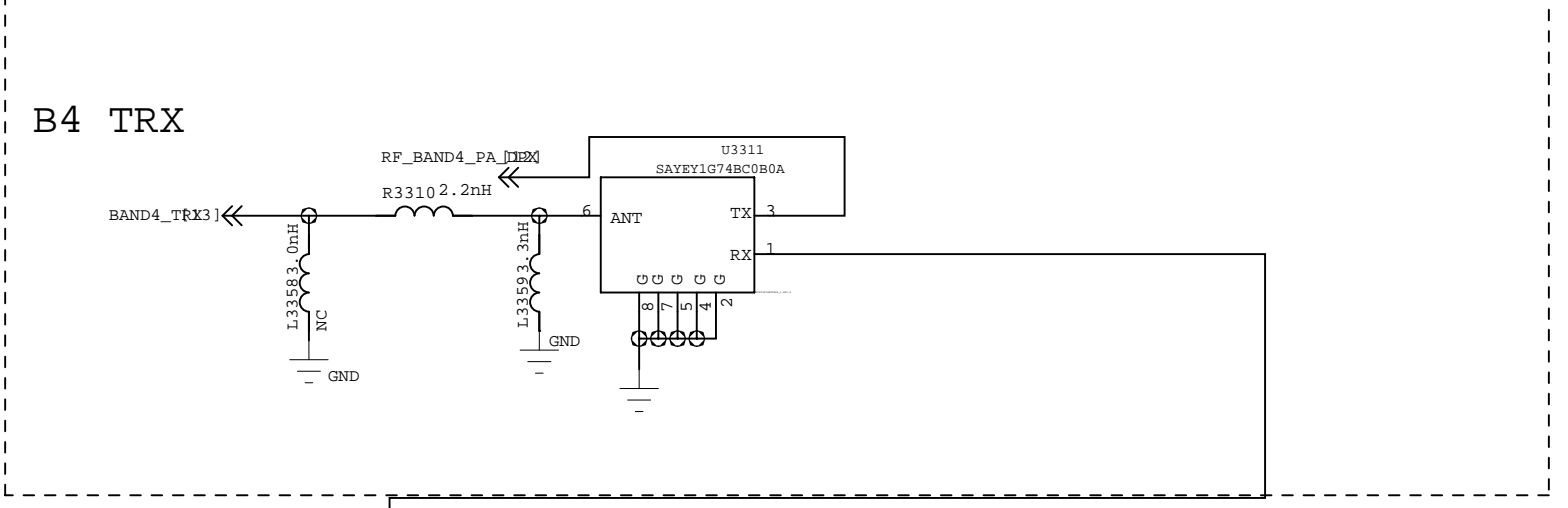
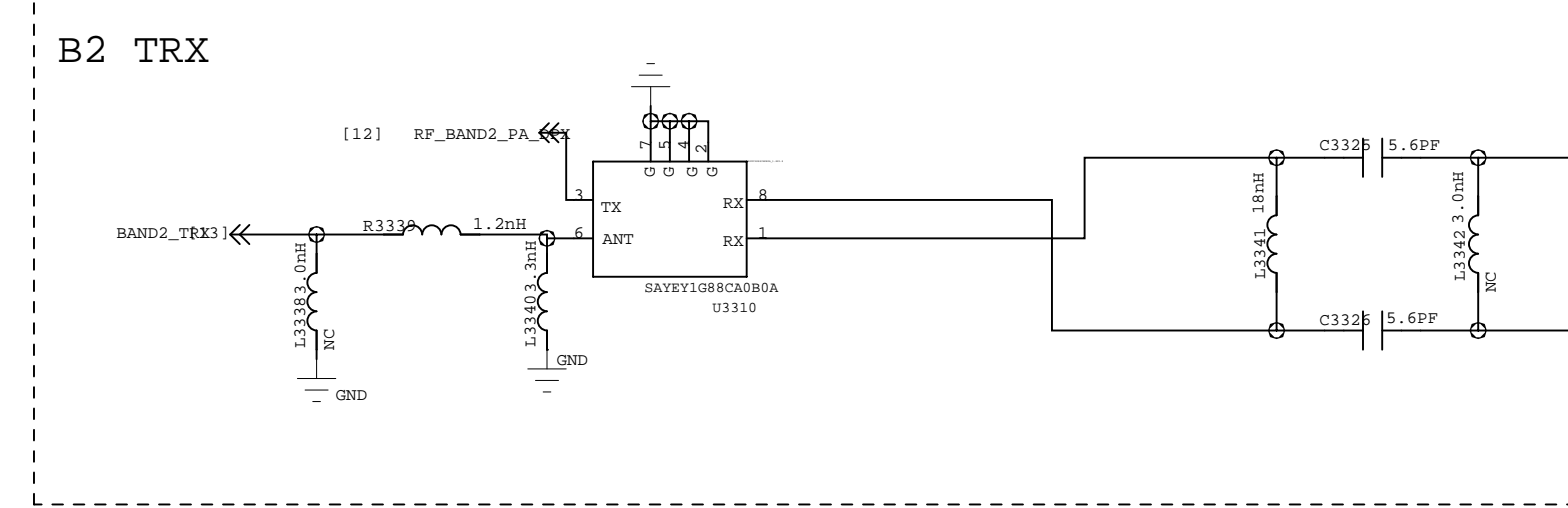
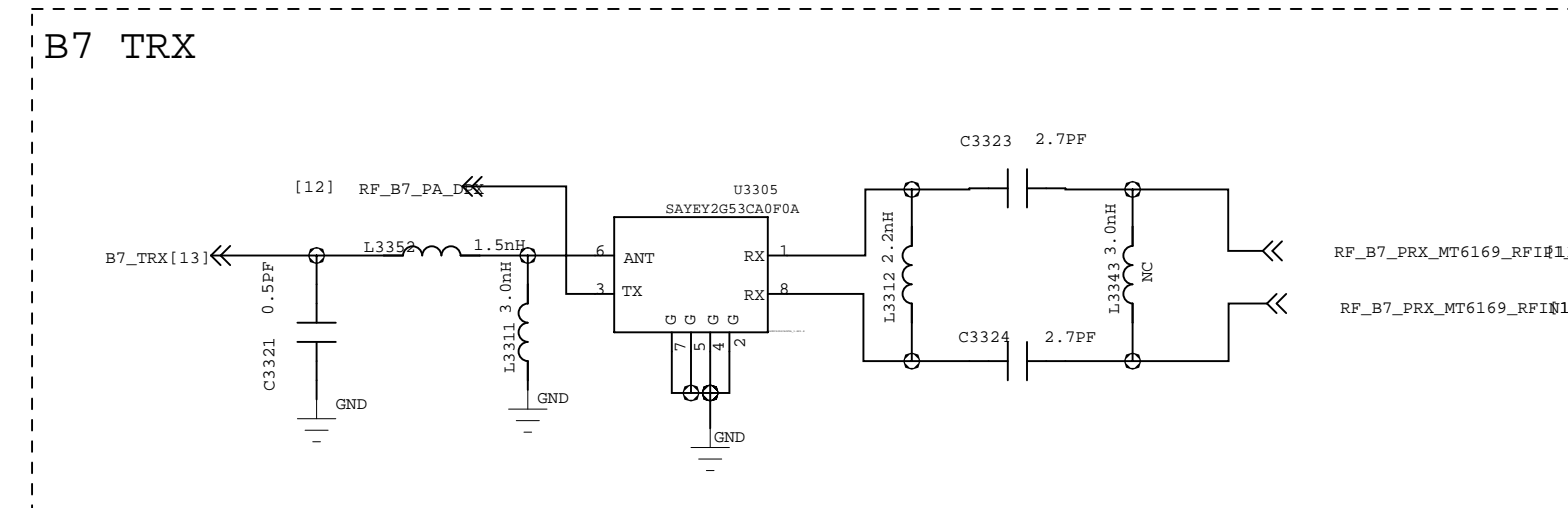
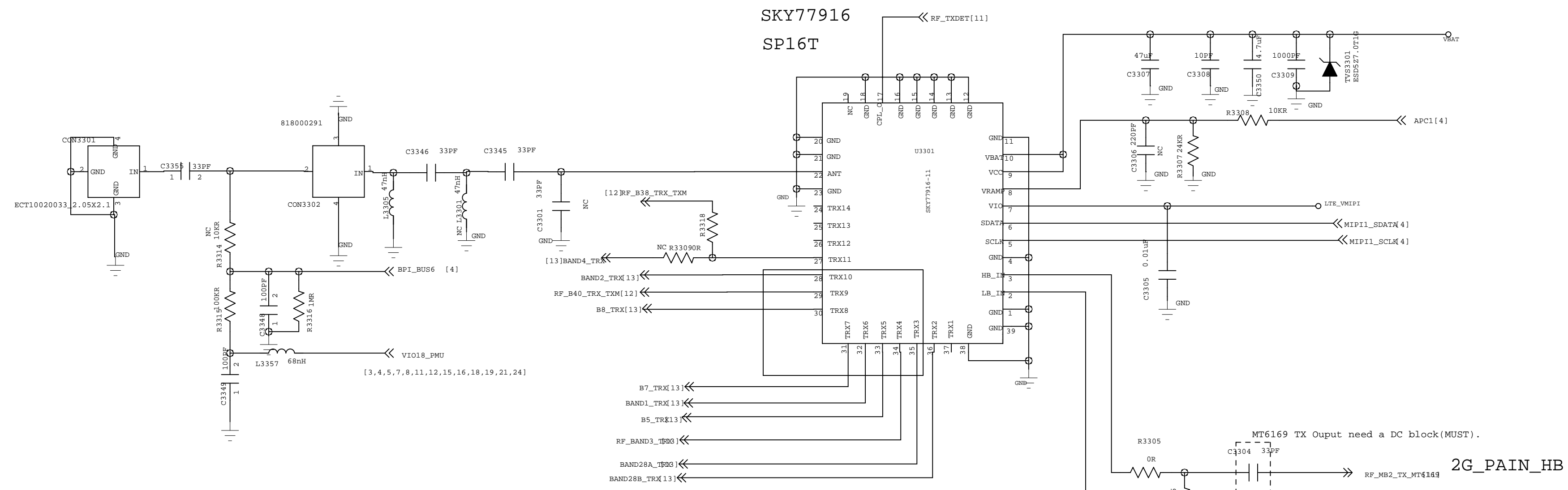
Far end Cap. For PMIC stability

Thermistor / To sense board level temperature

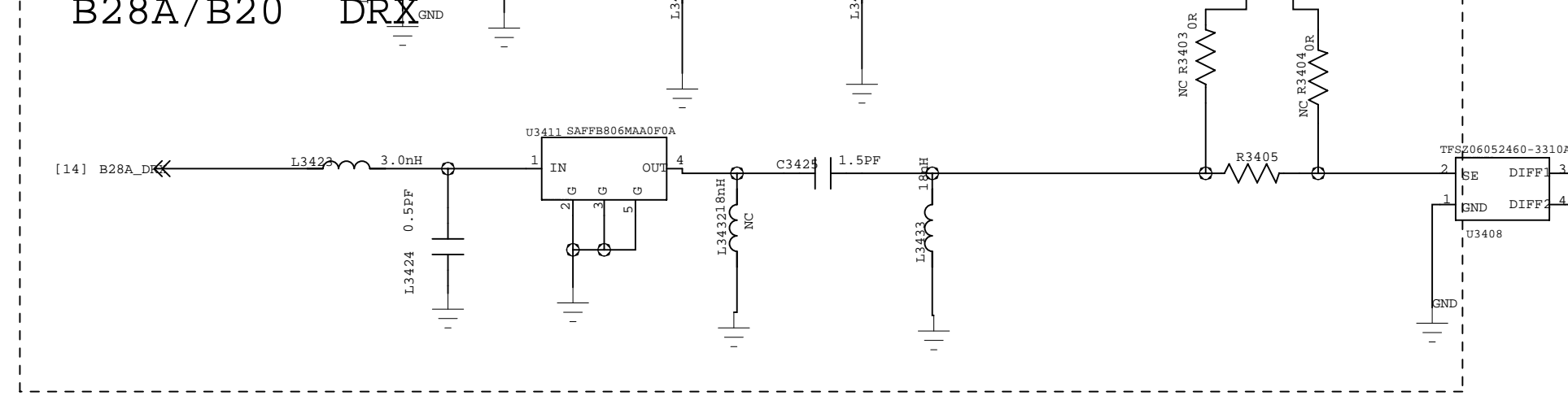
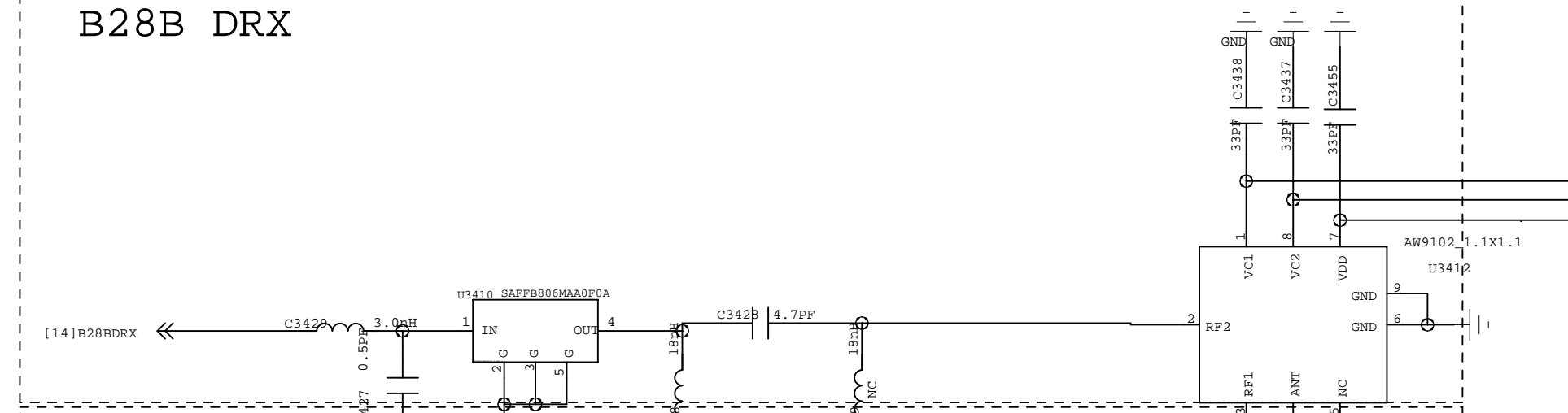
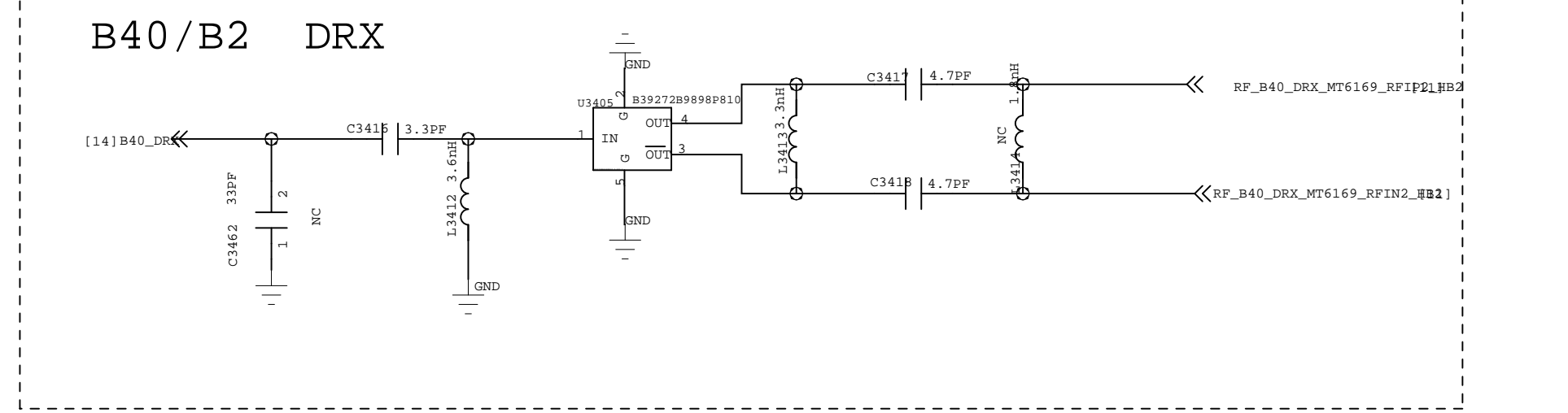
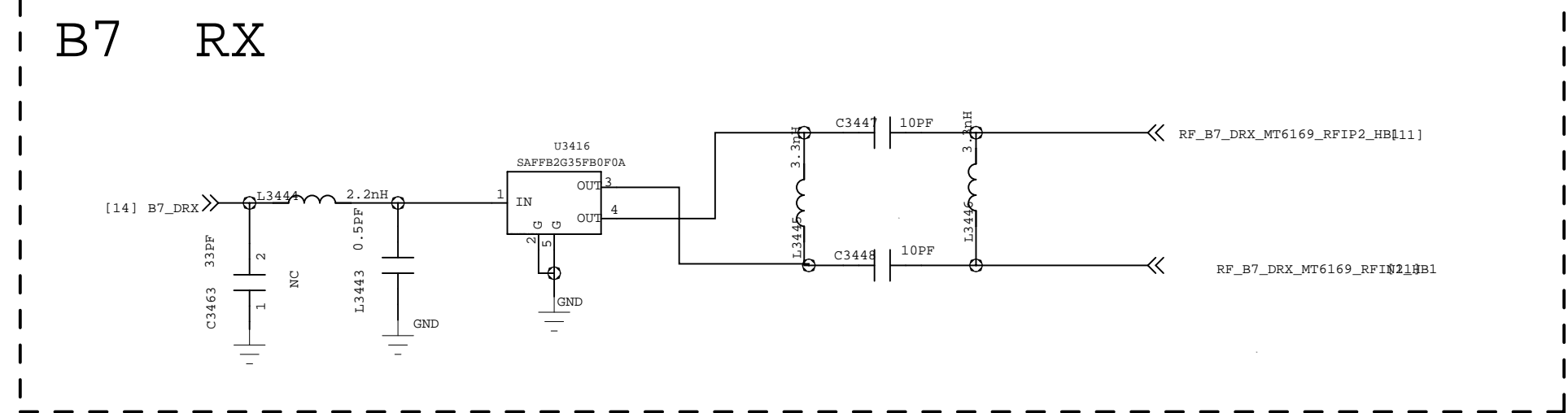
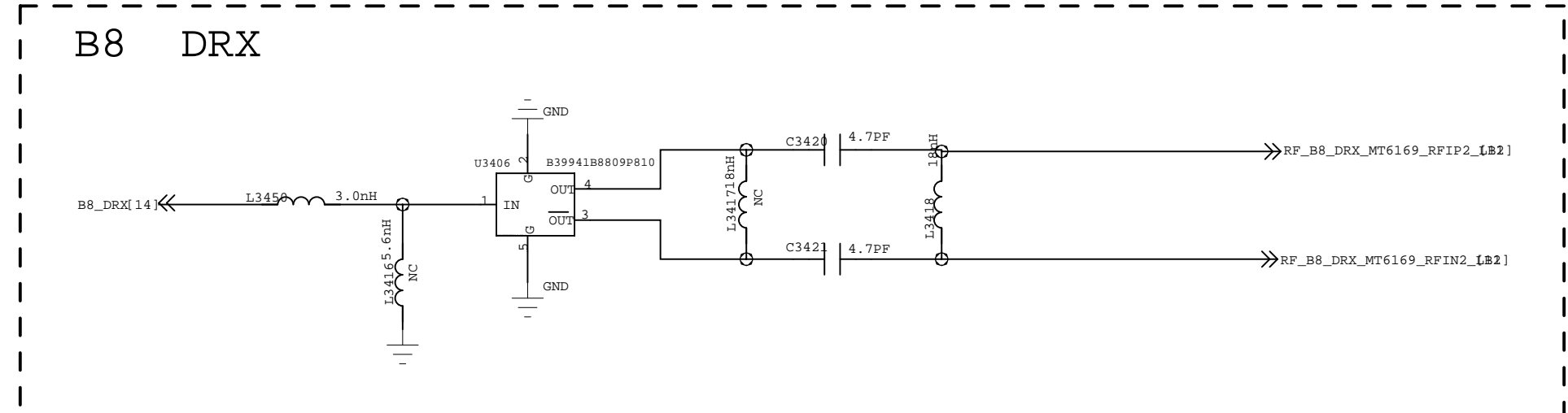
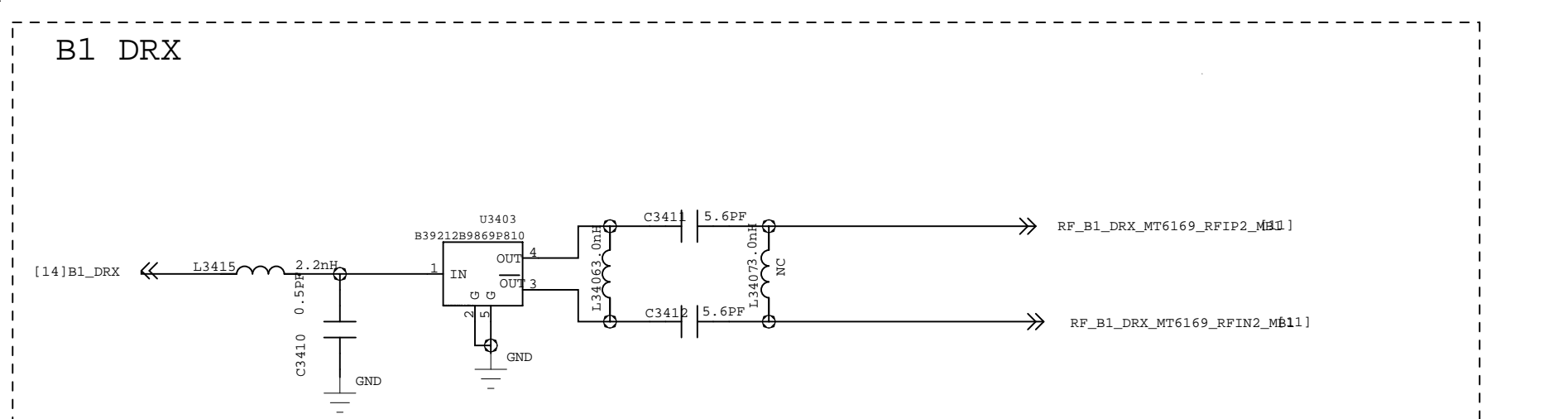
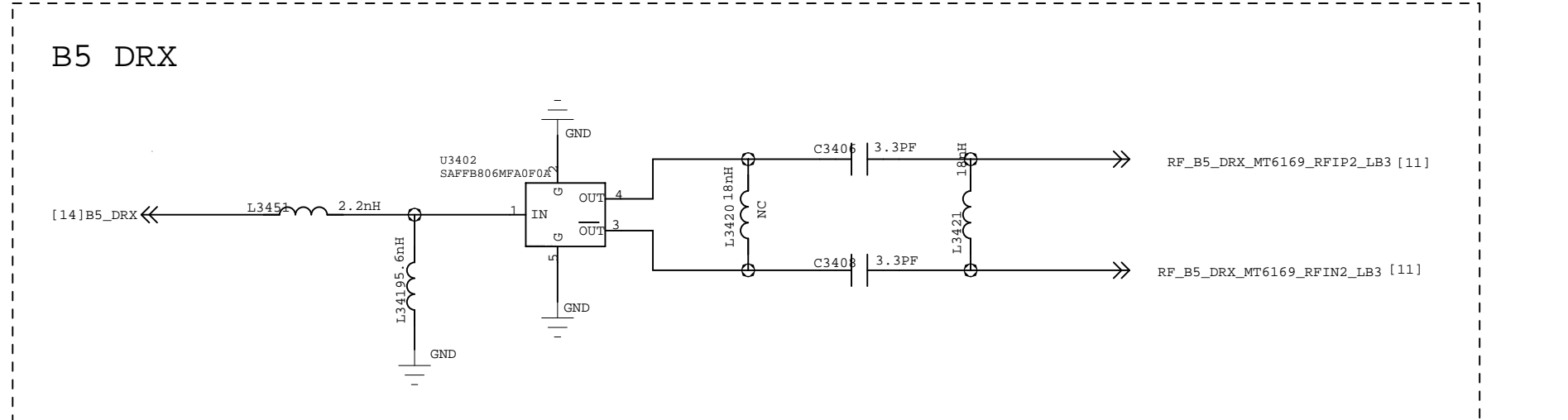
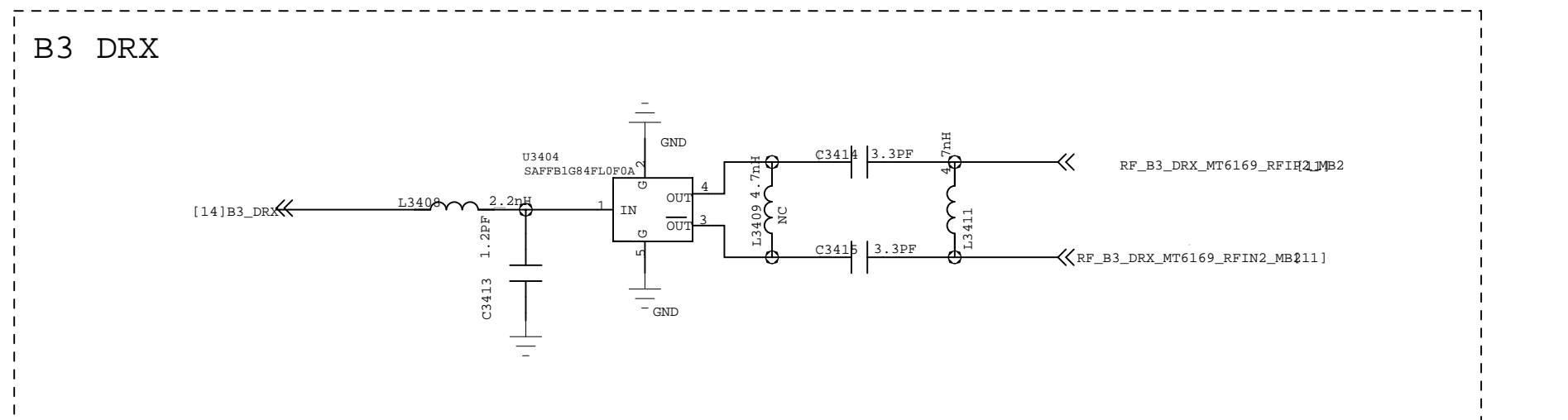
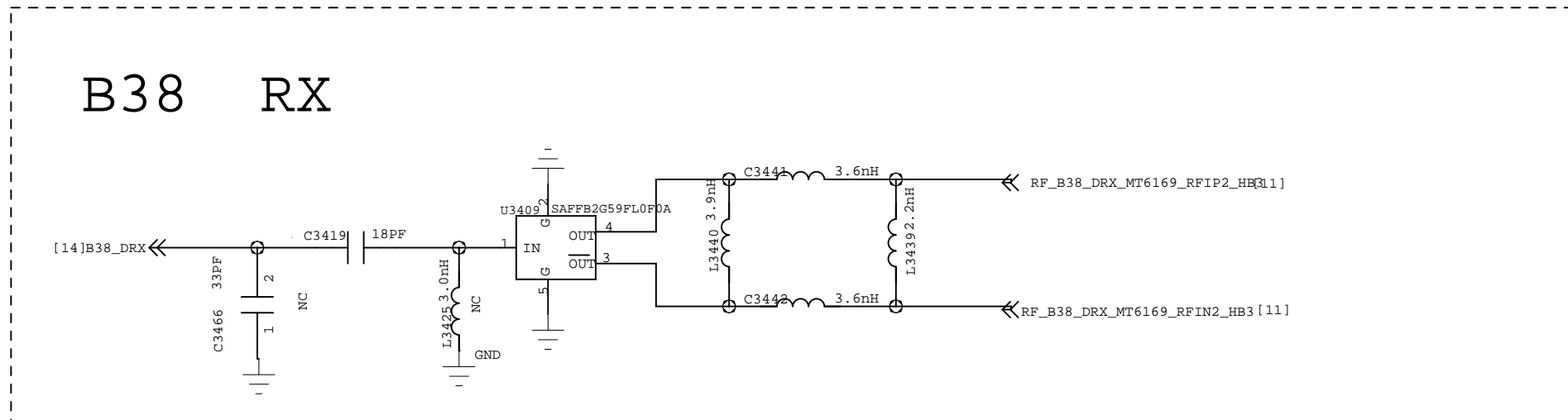
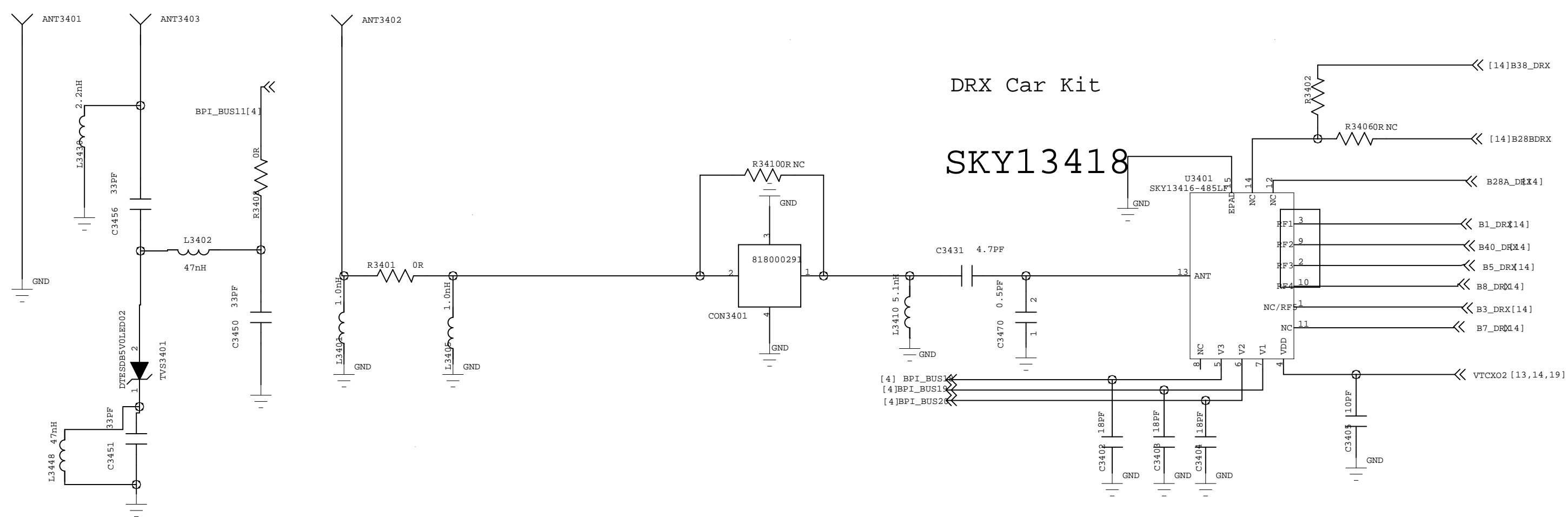


Title	32_RF_MT6169_RF_TX	
Size D	Yude Confidential	
Data	April 5, 2015	Sheet 32 of 99

Power trace	PCB line width	MAX current
VBAT	2.5mm (Min 2.0mm)	
LTE_VMIPI	0.15mm	



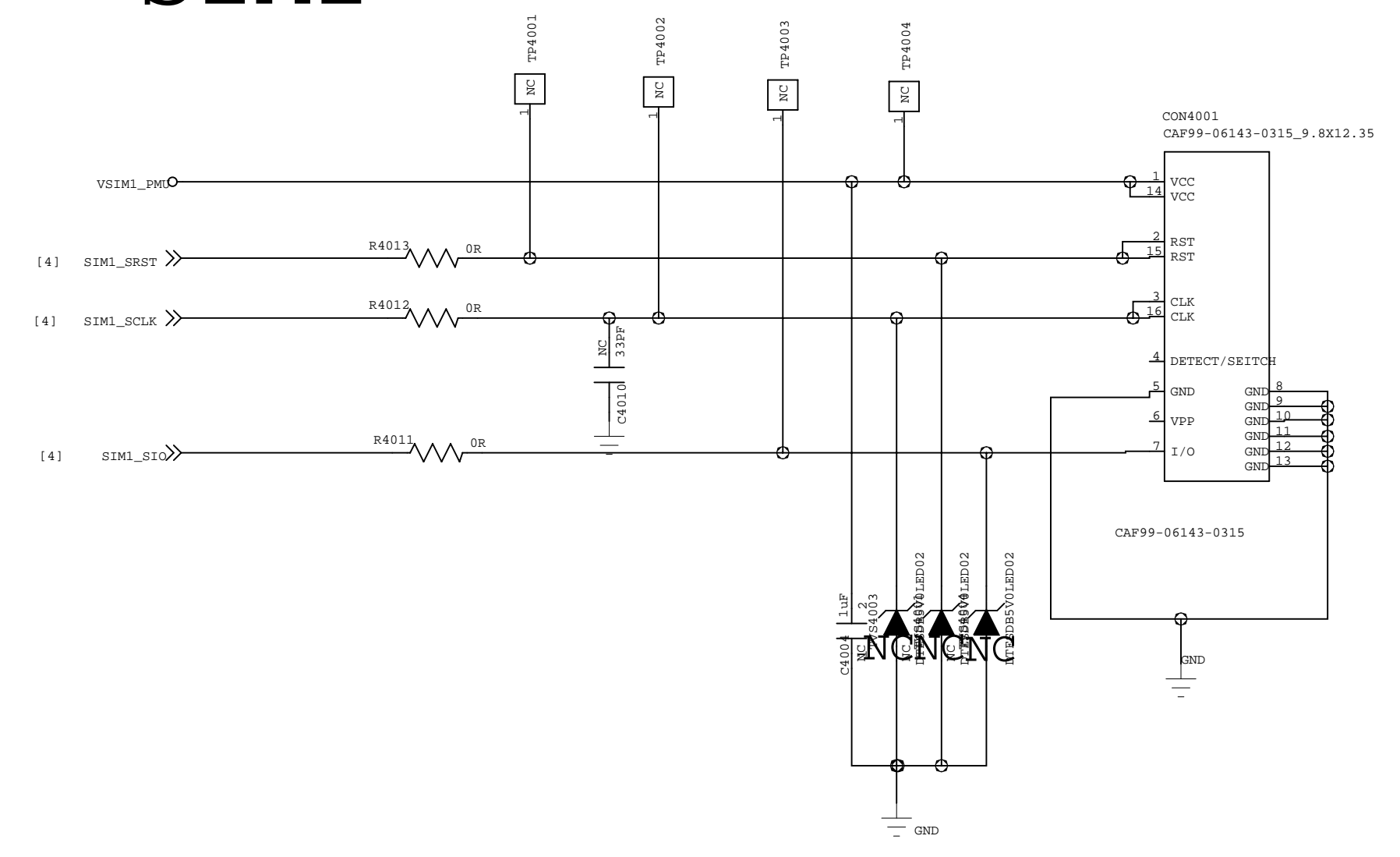
Power trace	PCB line width	MAX current
VTCX02	0.15mm	50uA



Title	34_RF_MT6169_RF_DRX	
Size	D	Yude Confidential
Data	Nov 6, 2015	Sheet 34 of 99

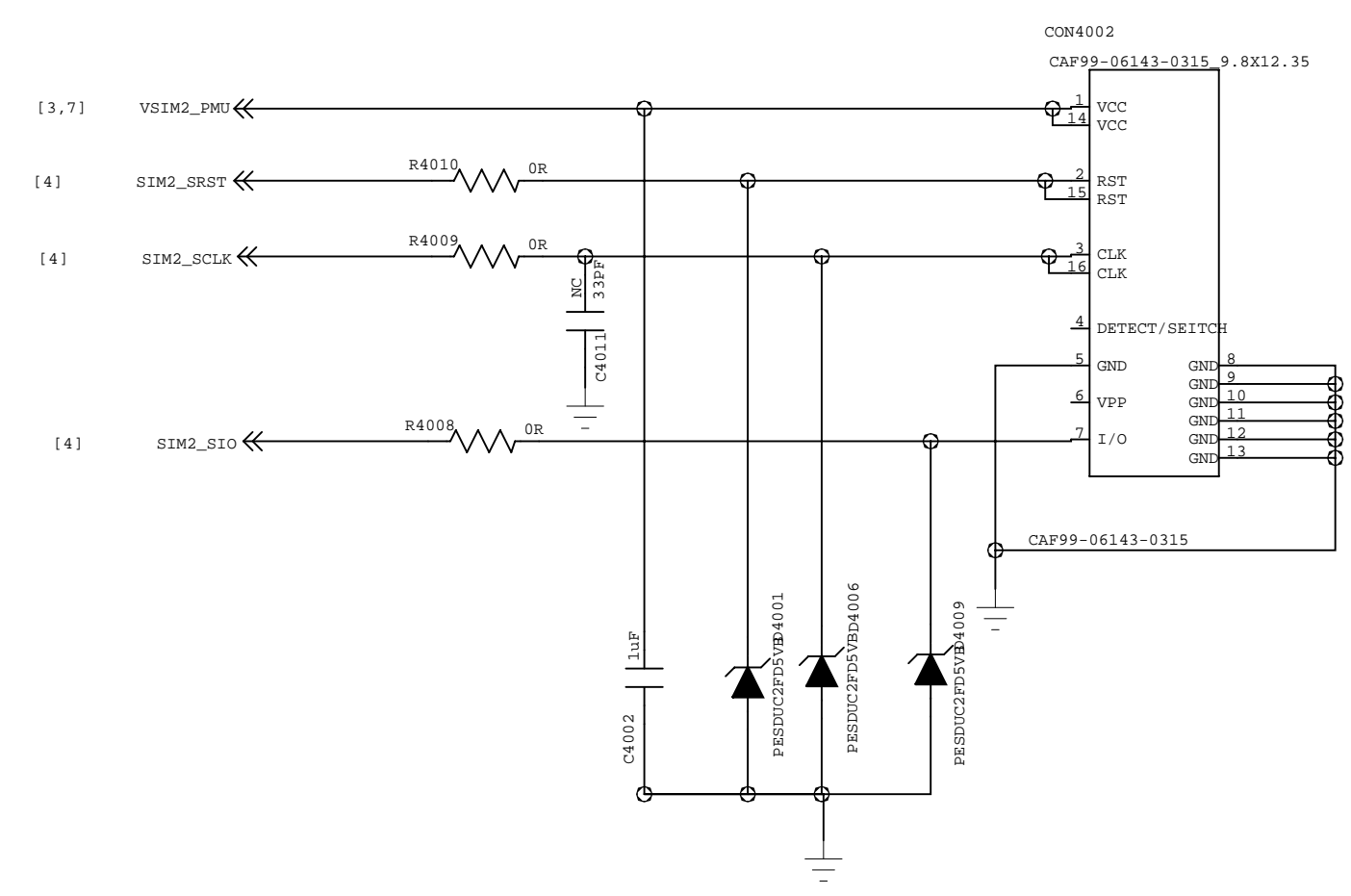
SIM1_sclk & SIM2_sclk shielding by GND

SIM1



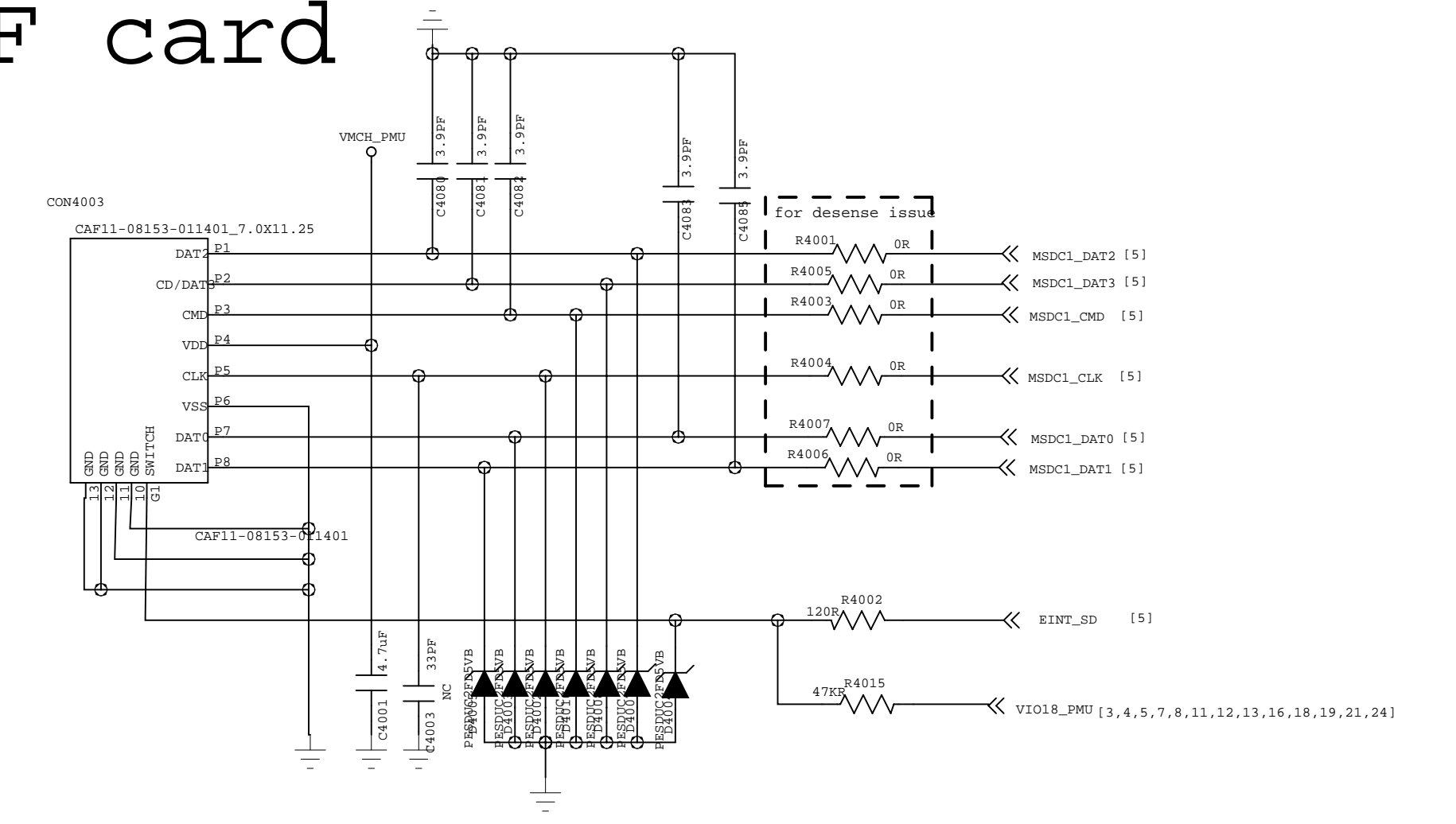
checked

SIM2



checked

TF card



checked

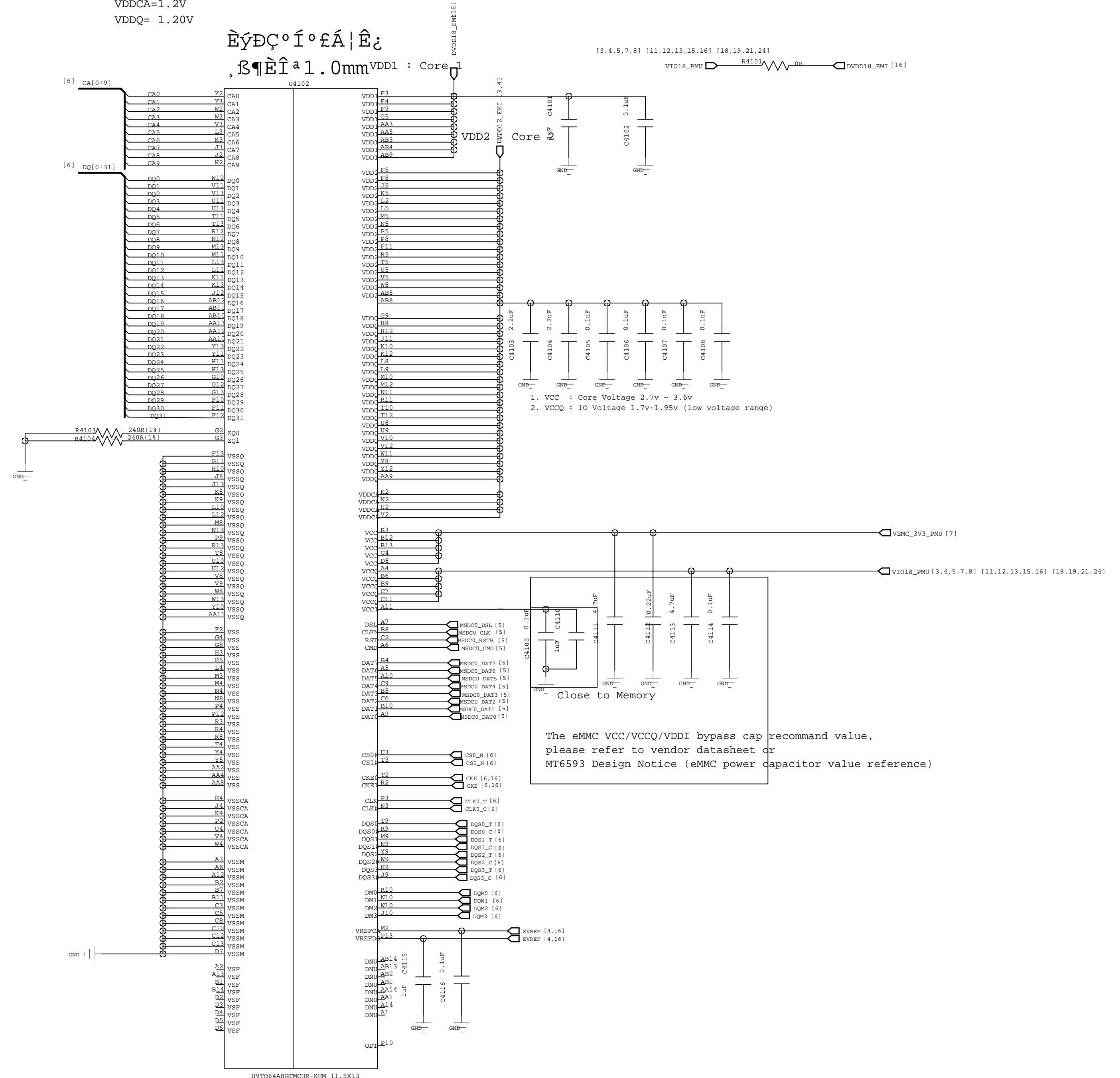
Connect to AP	
DQ[0..31]	DQ[0..31]
CA[0..9]	CA[0..9]
CS0_N	CS0_N
CS1_N	CS1_N
CKE	CKE
DQM0	DQM0
DQM1	DQM1
DQM2	DQM2
DQM3	DQM3
DQS0_C	DQS0_C
DQS1_C	DQS1_C
DQS2_C	DQS2_C
DQS3_C	DQS3_C
DQS0_T	DQS0_T
DQS1_T	DQS1_T
DQS2_T	DQS2_T
DQS3_T	DQS3_T
CLK0_T	CLK0_T
CLK0_C	CLK0_C
VREF_CA	VREF_CA
VREF_DQ	VREF_DQ
MSDC0_RSTB	MSDC0_RSTB
MSDC0_CMD	MSDC0_CMD
MSDC0_CLK	MSDC0_CLK
MSDC0_DSL	MSDC0_DSL
MSDC0_DAT0	MSDC0_DAT0
MSDC0_DAT1	MSDC0_DAT1
MSDC0_DAT2	MSDC0_DAT2
MSDC0_DAT3	MSDC0_DAT3
MSDC0_DAT4	MSDC0_DAT4
MSDC0_DAT5	MSDC0_DAT5
MSDC0_DAT6	MSDC0_DAT6
MSDC0_DAT7	MSDC0_DAT7

Power I/F	
VIO18_PMU	VIO18_PMU
VEMC_3V3_PMU	VEMC_3V3_PMU
DVDD12_EMI	DVDD12_EMI

eMMC+LPDDR3 16GB eMMC + 8Gb LPDDR3

221 Ball, 0.5mm pitch

VDD1=1.8V
VDD2=1.20V
VDDCA=1.2V
VDDQ= 1.20V

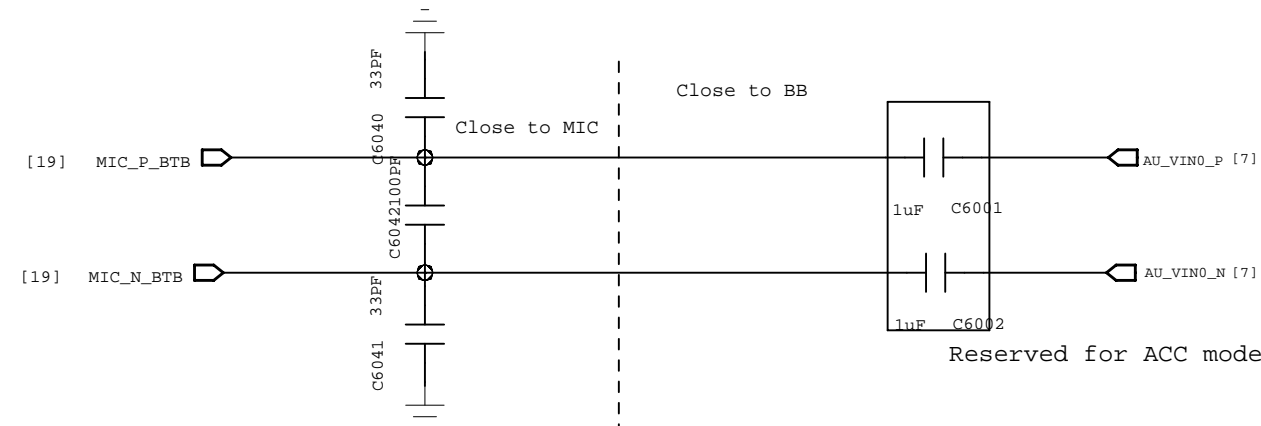


Speaker NC

Based on your system level design , if better
desense performance is needed on your
system.

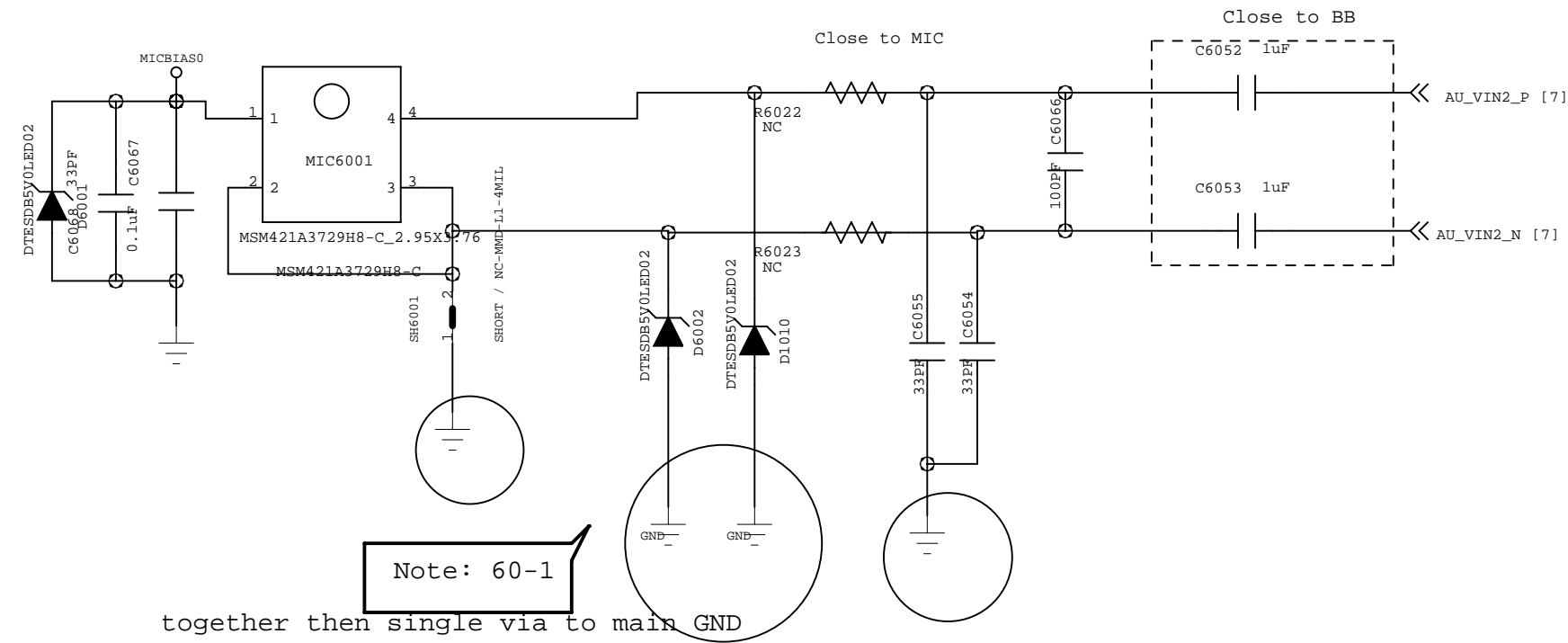
Based on your system level design , if
better ESD performance is needed on
your system.

Handset Microphone 1



Based on your system level design, if better
audio performance is needed on your
system, please reserve for ACC mode

Second MIC NC



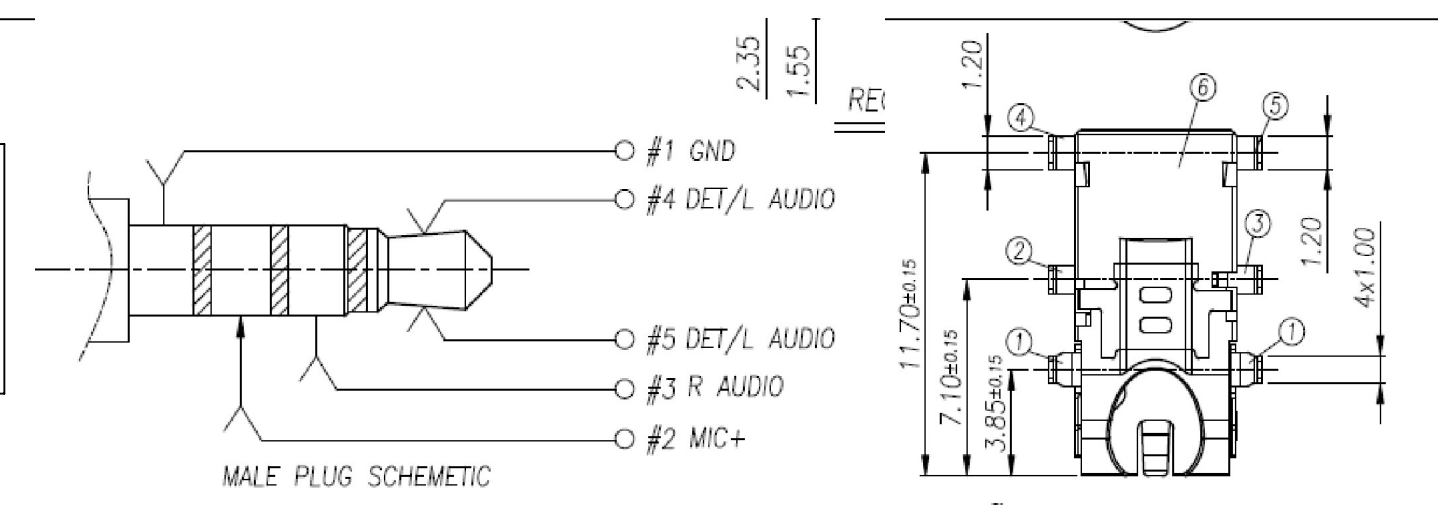
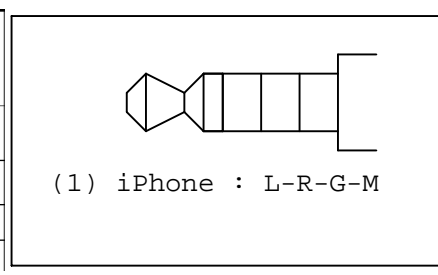
Note: 60-1

together then single via to main GND

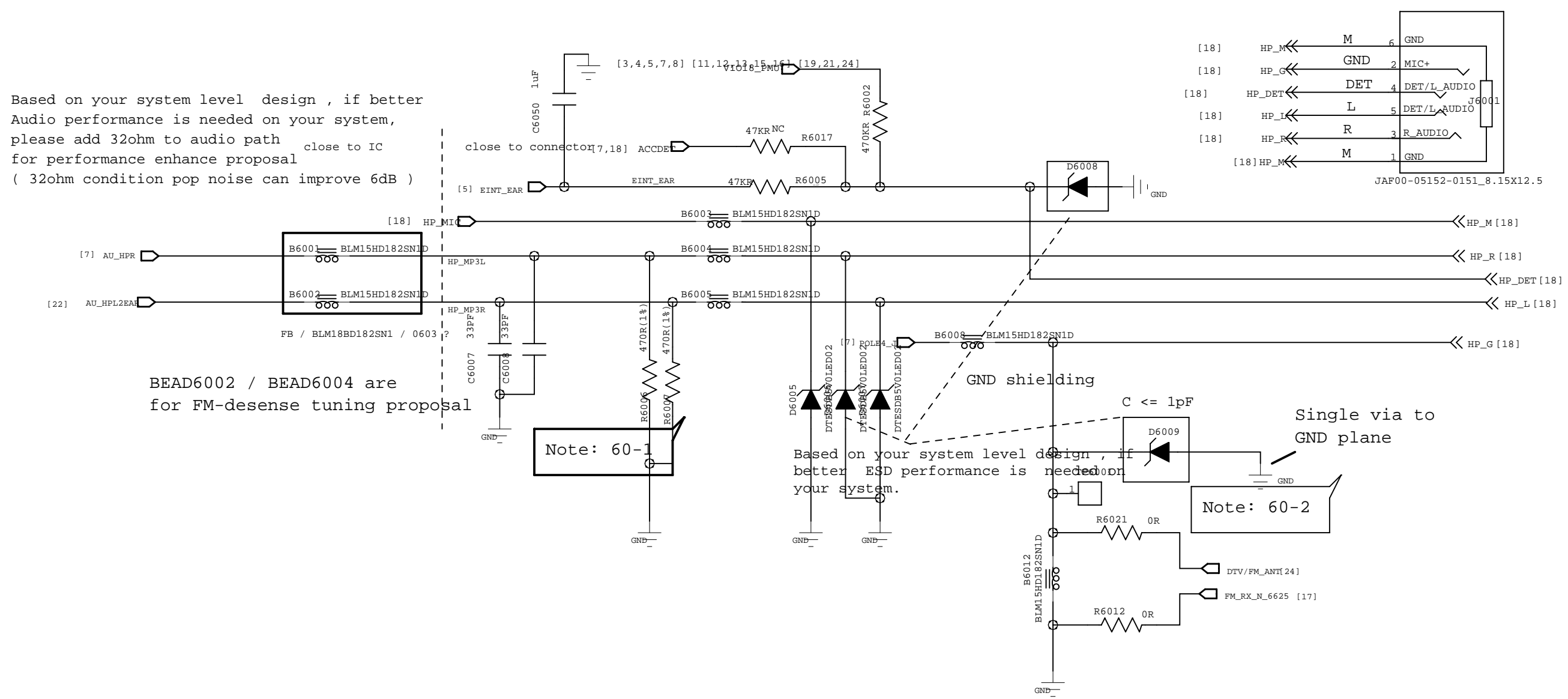
checked

Earphone AudiõÀ±±±

DIMENSION IN mm		LCN Shenzhen Linkconn Electronics Co.,Ltd.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		APR:	TITLE: #3.5 AUDIO JACK (DIP) INSERT TYPE
.X±0.35	.X±.5'	DWG NO:	JAF00-05152-0151
.XX±0.25	.X±.3'	DRA:	PRM: CUSTOMER DRAWING
.XXX±0.15	.XX±.1'	DRA: pengzhiqun 2015.07.31	SIZE: A4 SCALE: 3:1 SHEET: 2/2 REV: A



Based on your system level design , if better
Audio performance is needed on your system,
please add 32ohm to audio path close to IC
for performance enhance proposal
(32ohm condition pop noise can improve 6dB)



BEAD6002 / BEAD6004 are
for FM-desense tuning proposal

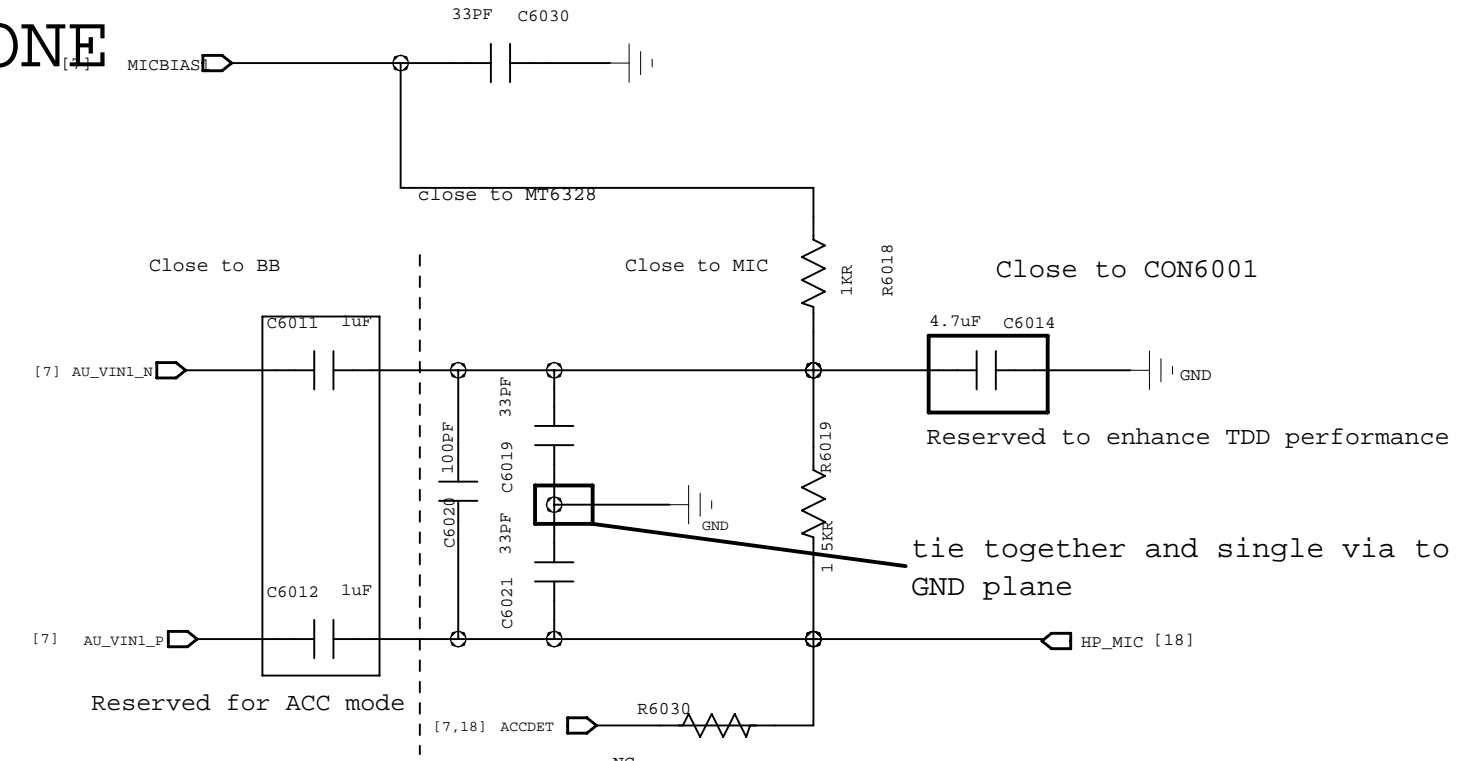
Note: 60-1

Based on your system level design , if
better ESD performance is needed on
your system.

Single via to
GND plane

Note: 60-2

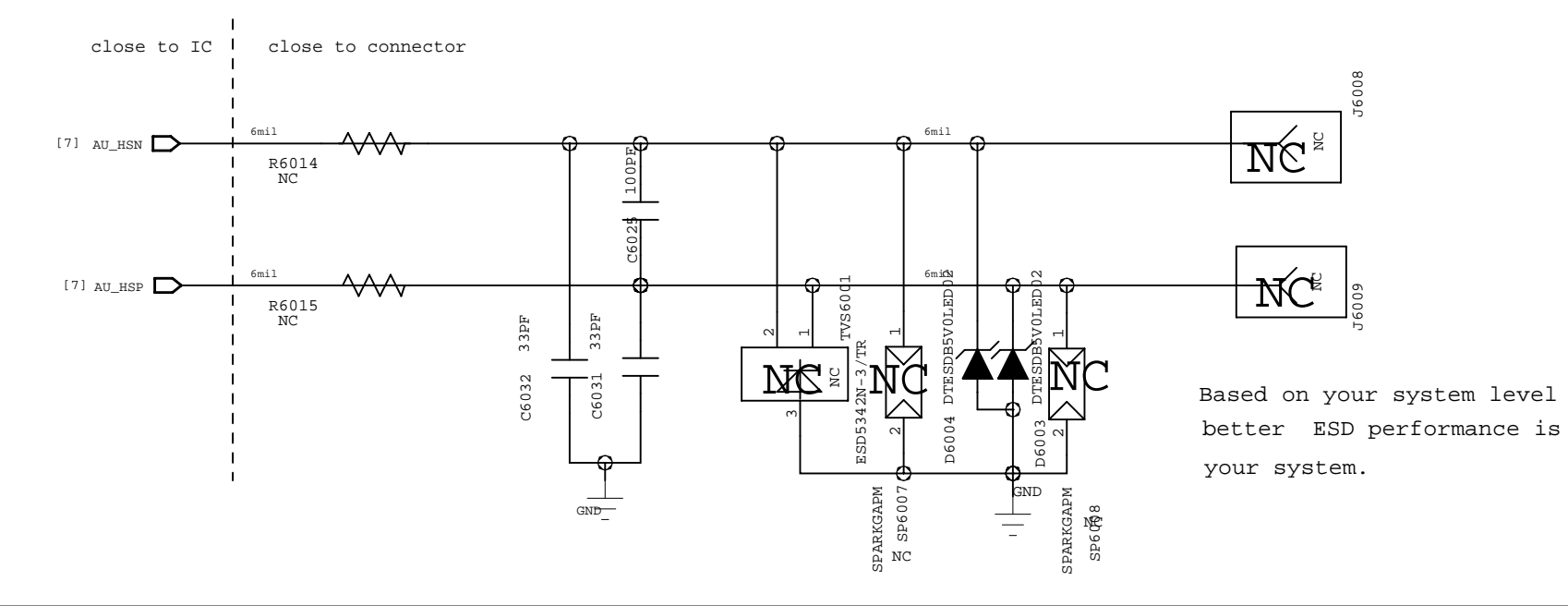
Earphone MICPHONE



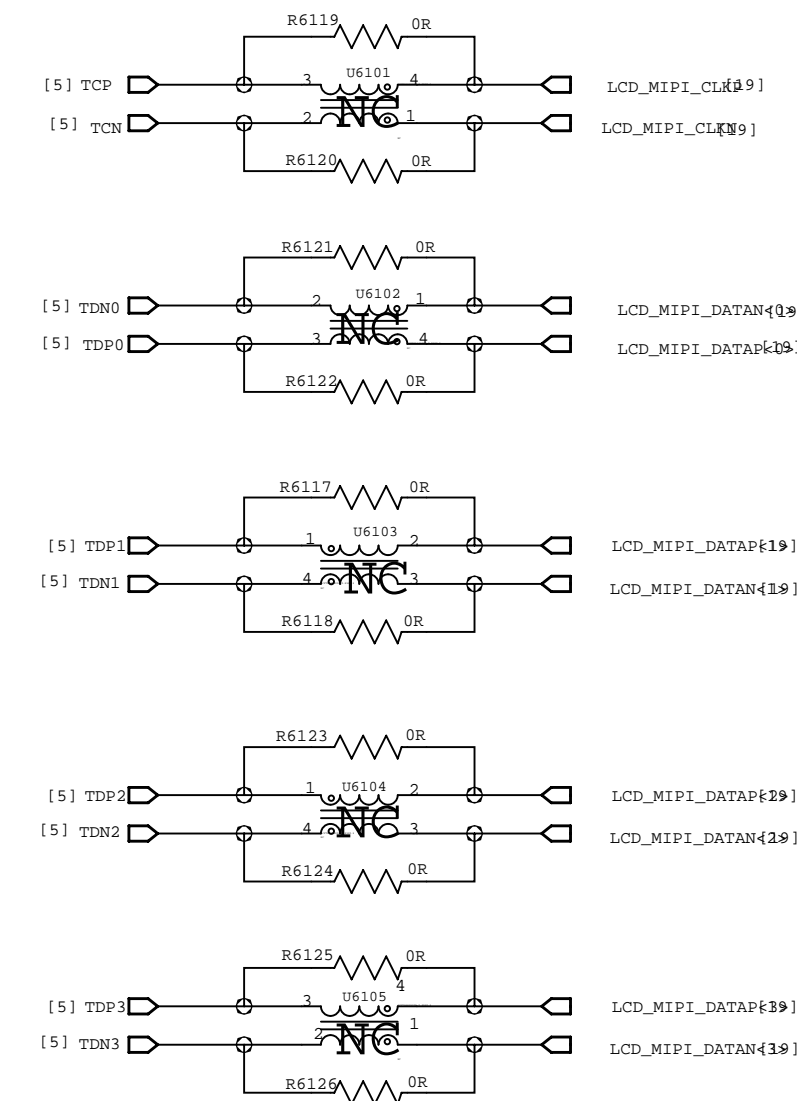
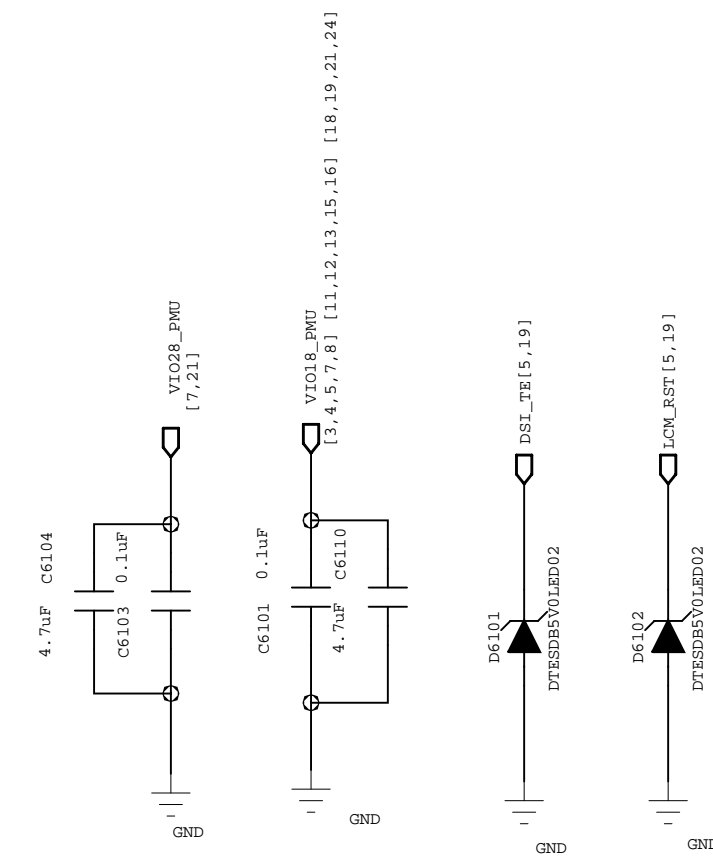
Reserved for ACC mode

tie together and single via to
GND plane

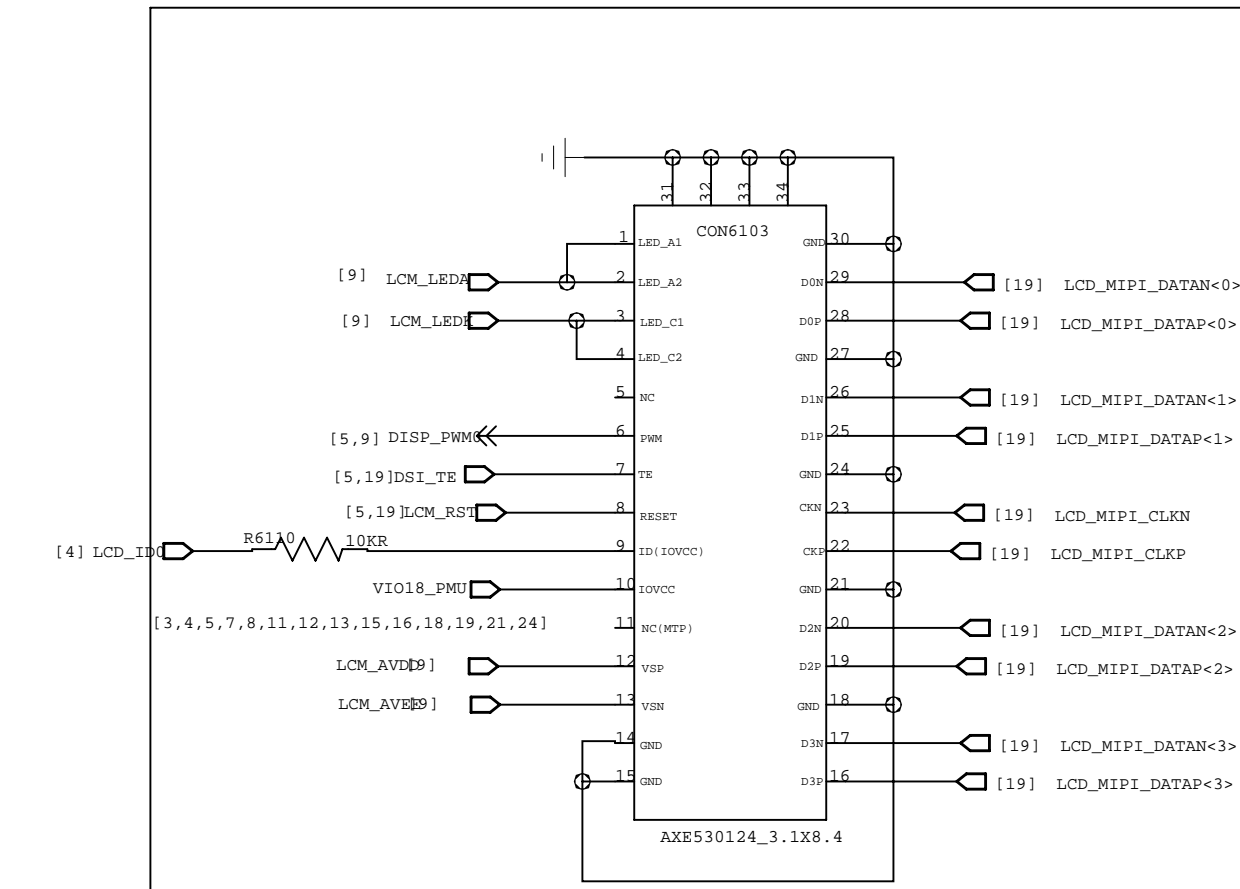
Receiver



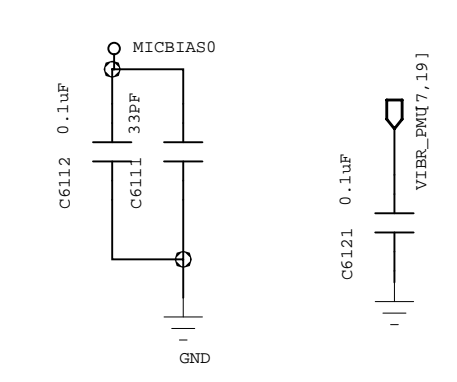
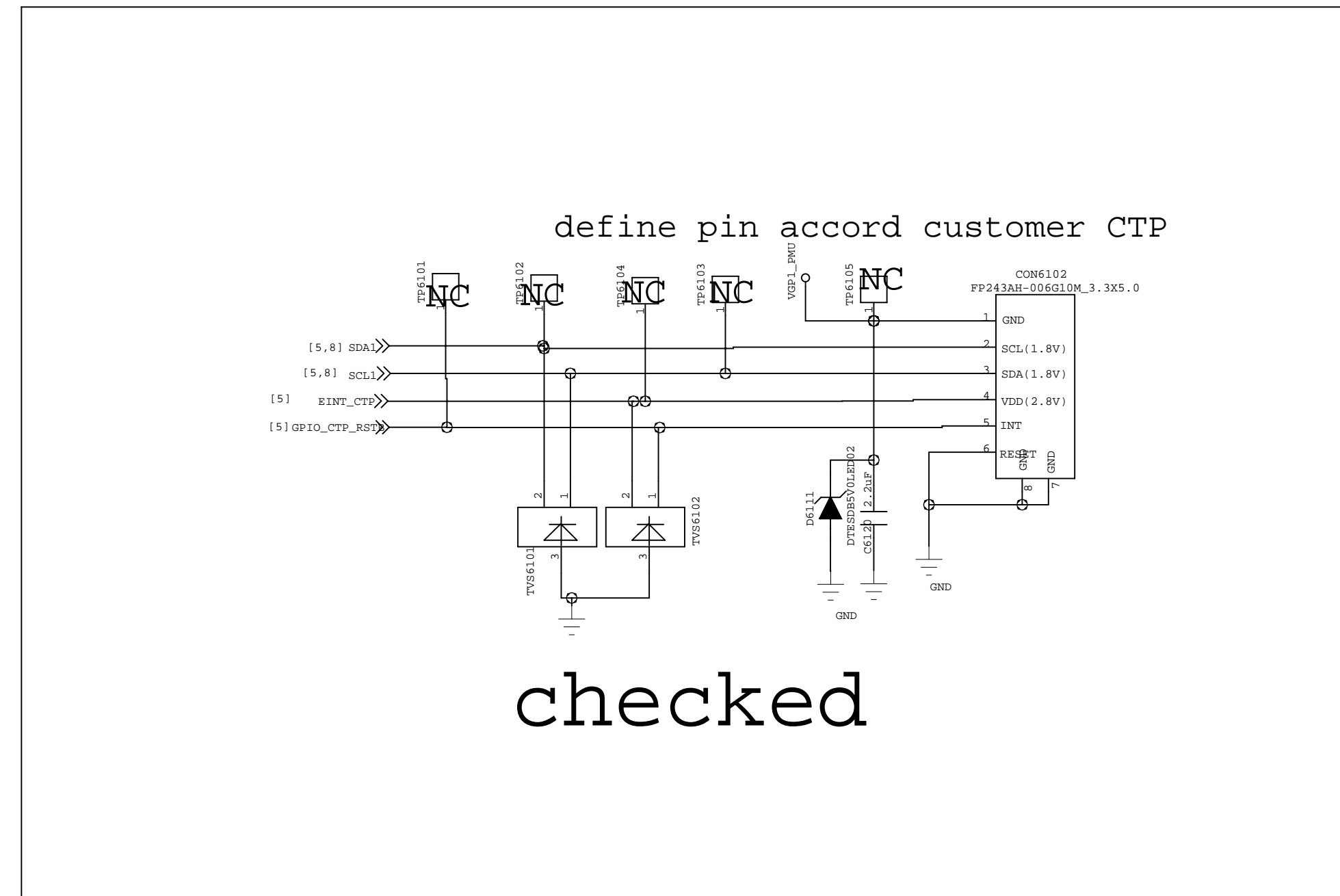
Based on your system level design , if
better ESD performance is needed on
your system.



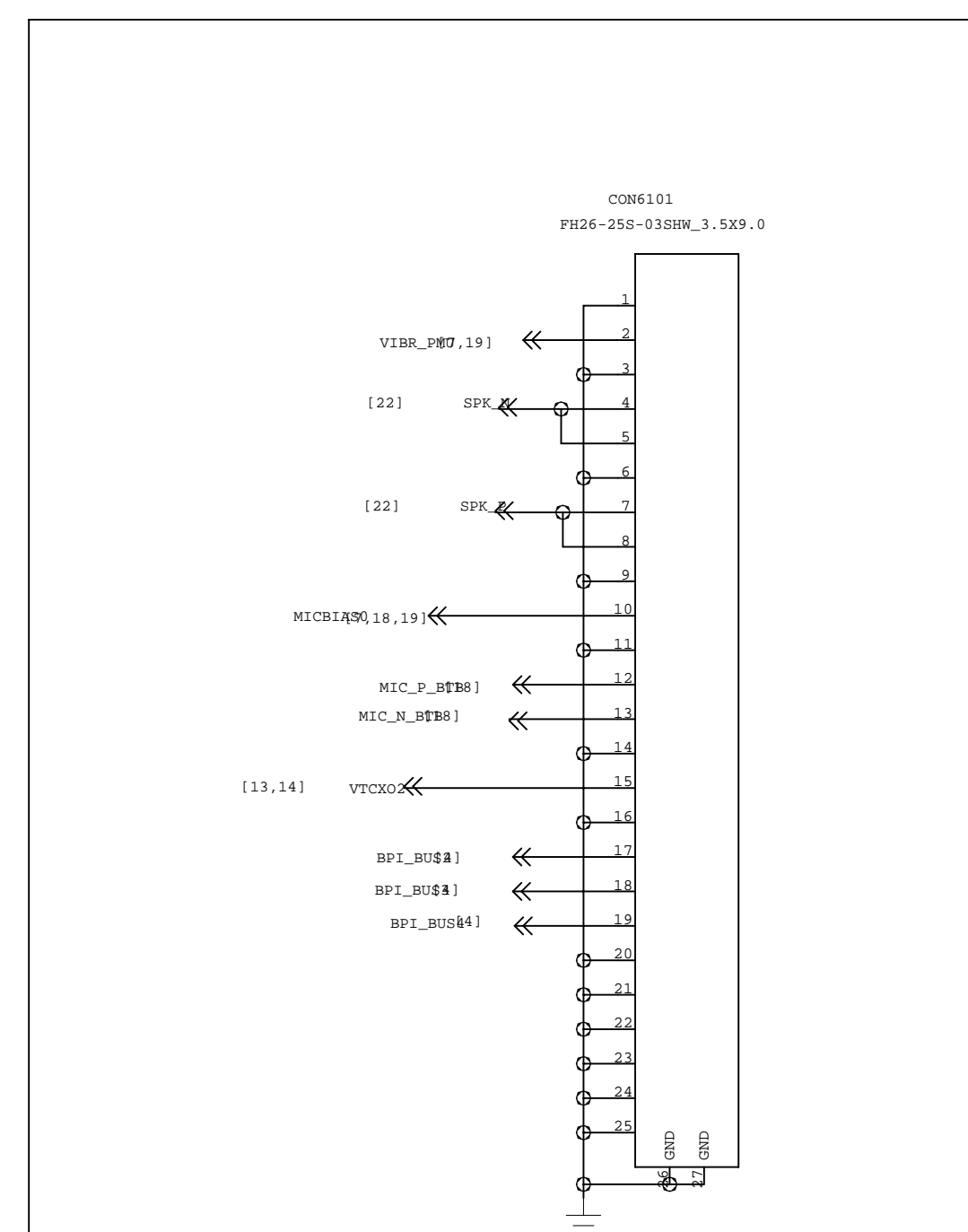
ÆÁÁ-½ÓÆ÷



530124 or 530127???

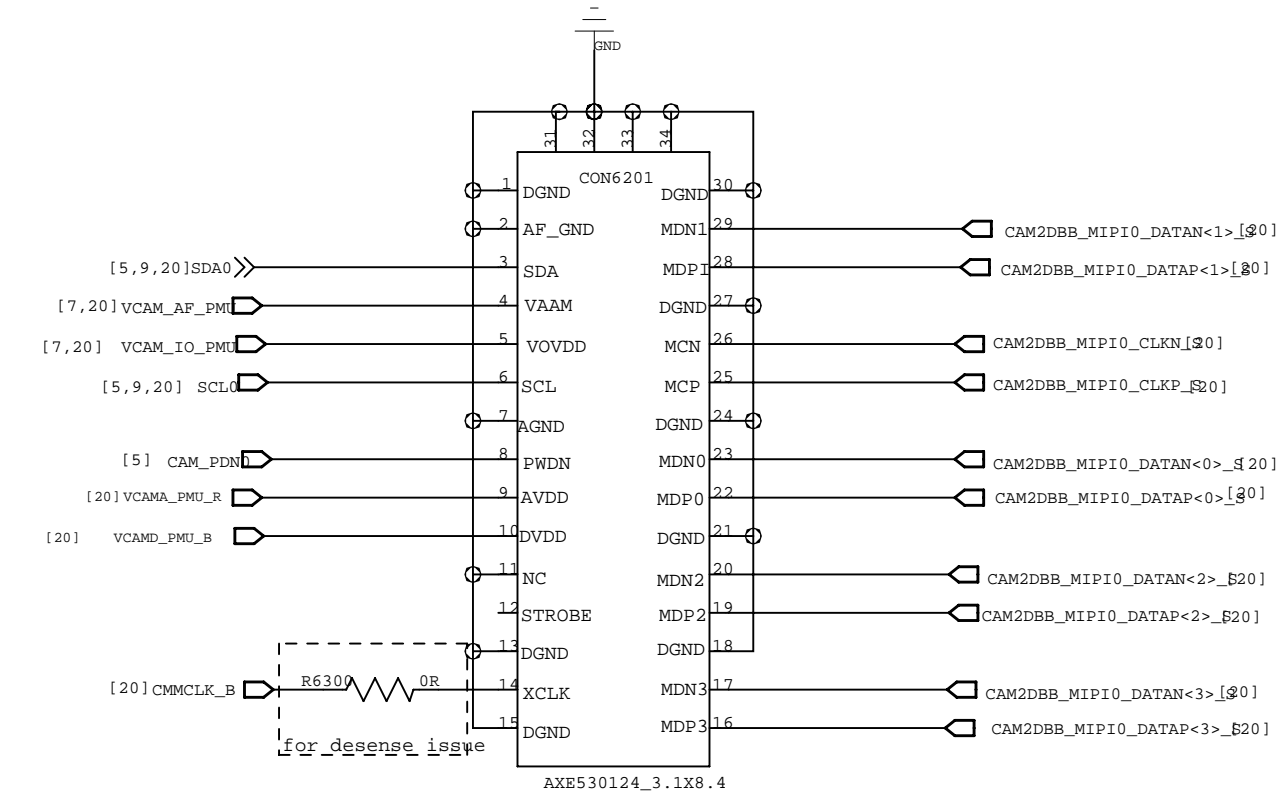
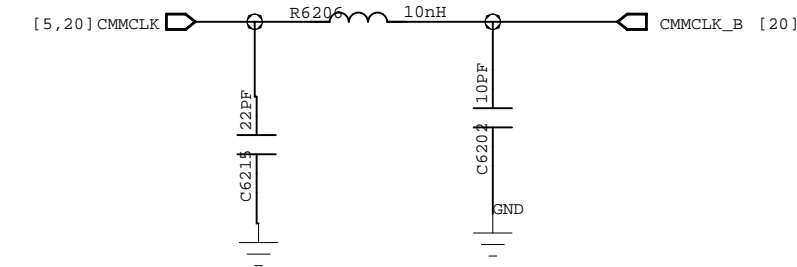
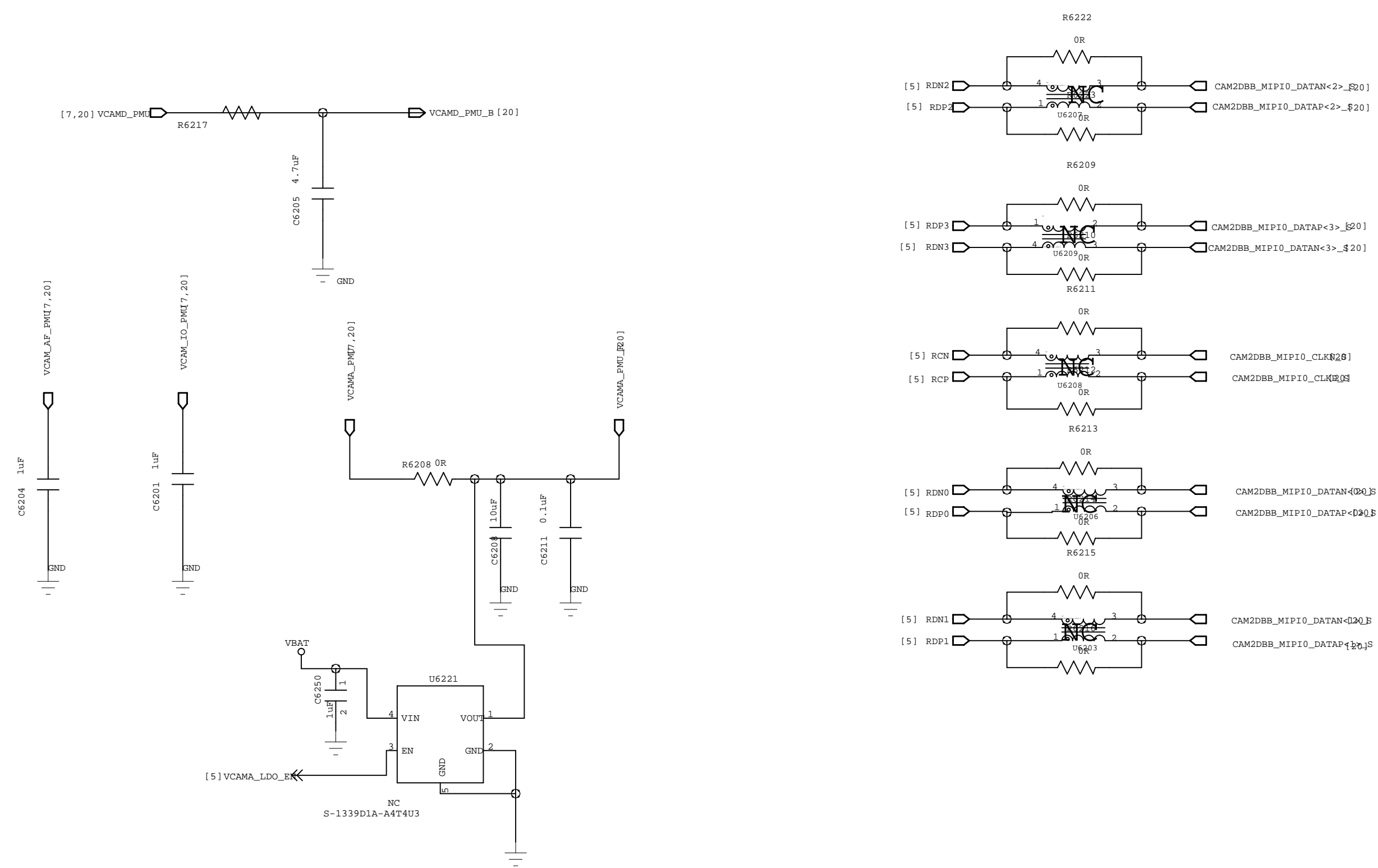


25PIN´óÐ; °áÁ-½ÓÆ÷ZIF

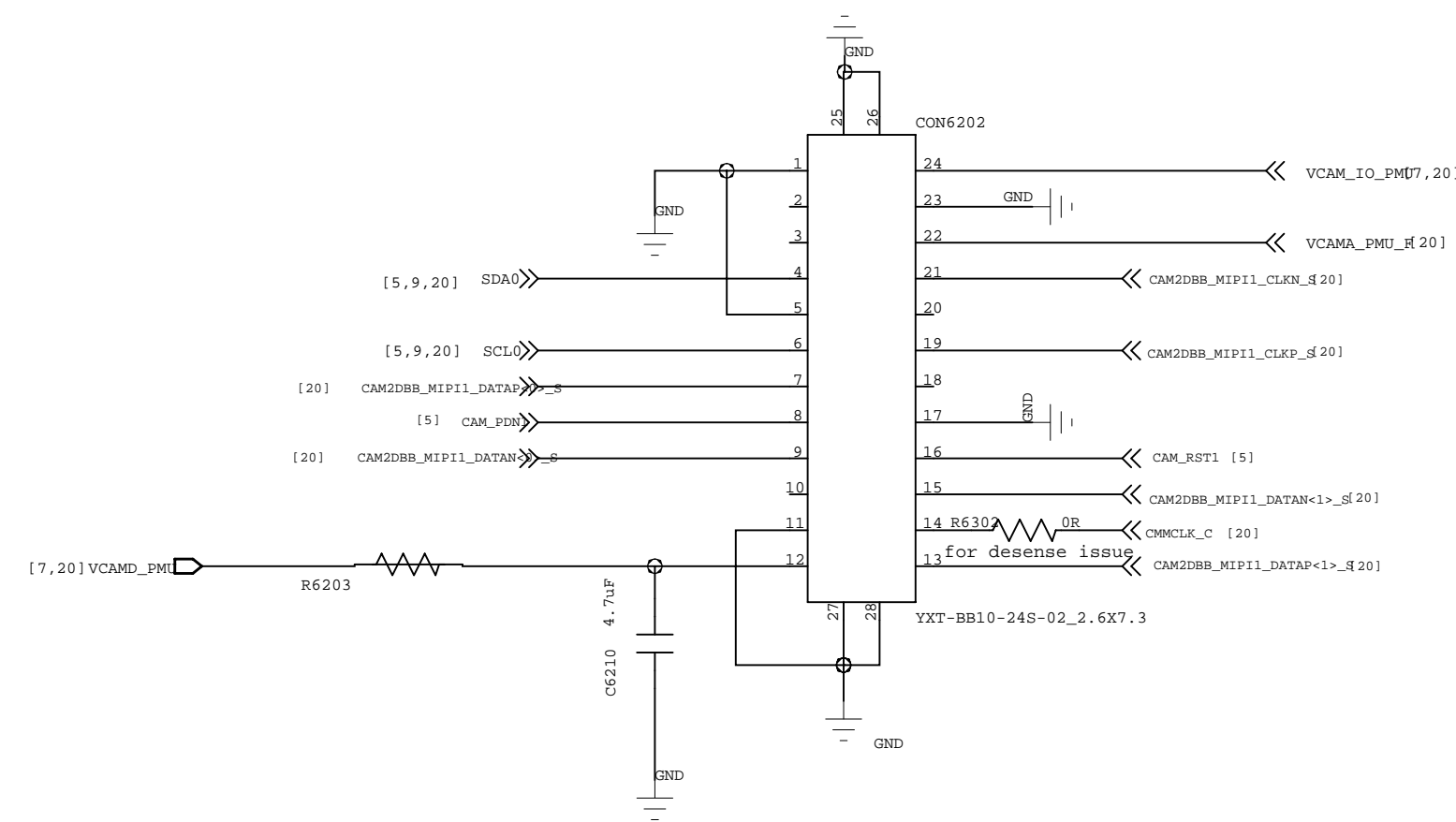
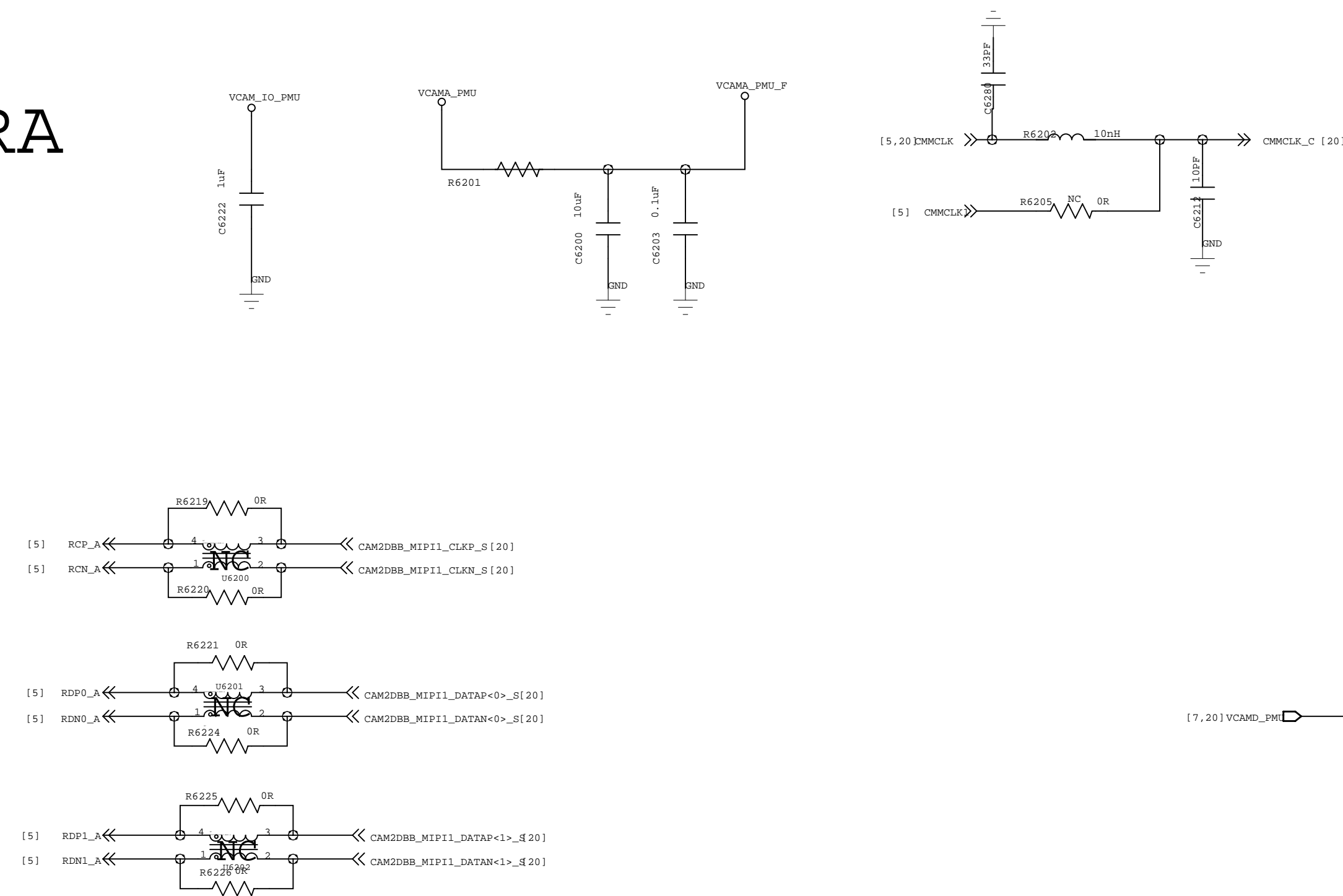


Title		61_PERI_LCD_CTP
Size	D	Yude Confidential
Data	Sep 14, 2016	Sheet 61 of 99

MAIN_CAMERA



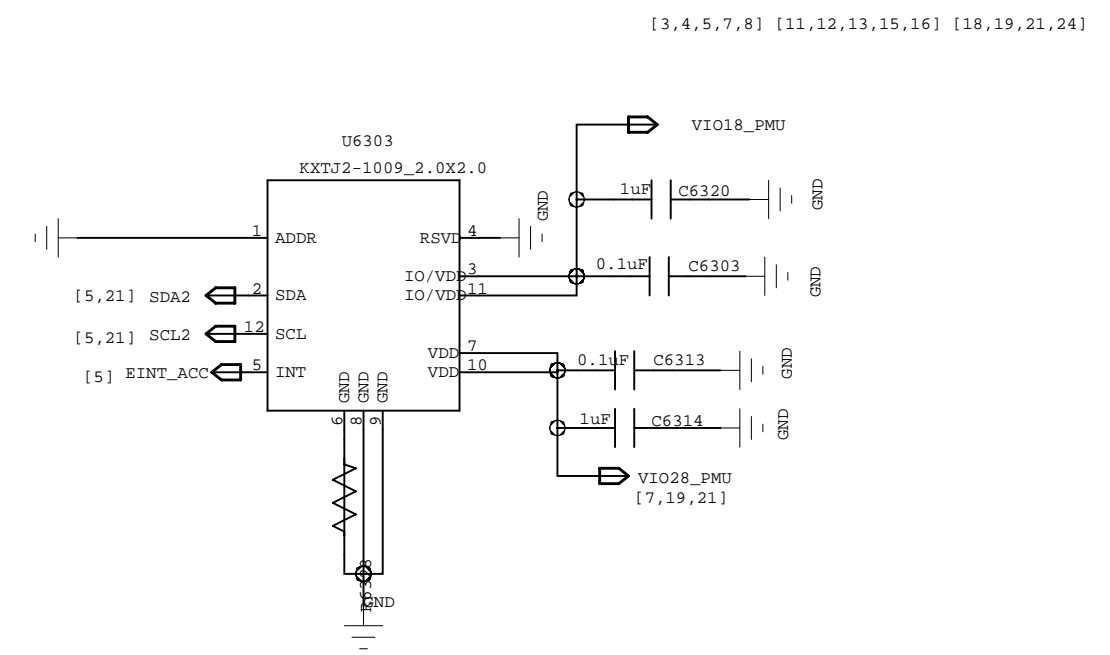
SUB_CAMERA



Need creat new sch,pcb

Title	62_PERI_CAMERA	
Size D	Yude Confidential	
Data	Sep 14, 2016	Sheet 11 of 99

G Sensor-3X



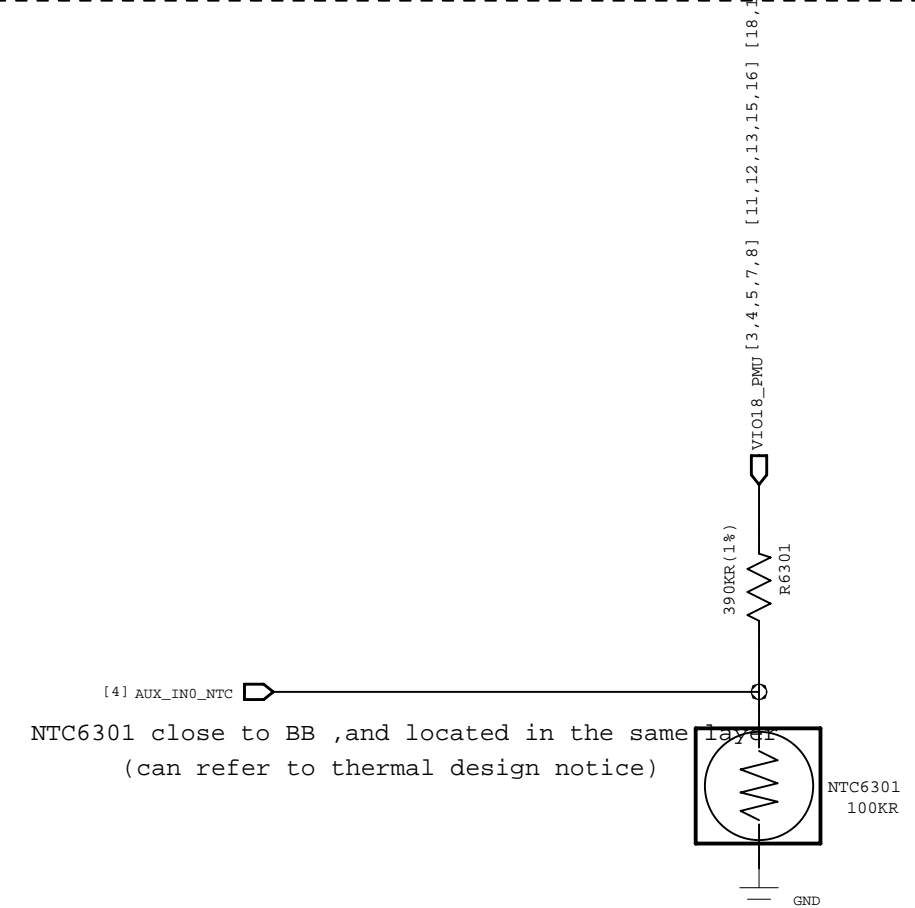
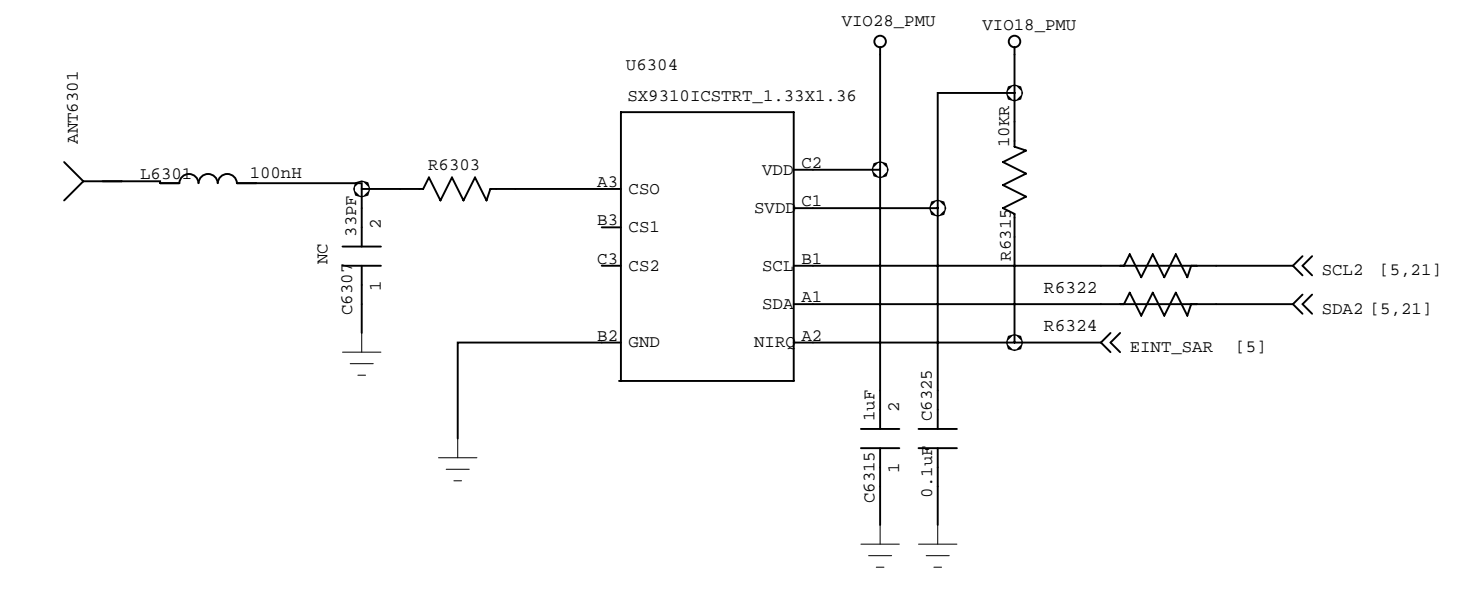
CS=1: IIC
 LIS3DHTR : SA0=0: IIC ADDRSS is 0x18H
 KXCJK-1113 : SA0=0: IIC ADDRSS is 0x1DH
 power down(communicating), I = 0.5uA

Configuration VS Chip

Fuction	U3001	C3004	C3005	C3006	R3003
G-Sensor	LIS3DHTR	NC	NC	NC	0
G-Sensor	KXCJK-1113	NC	NC	NC	0

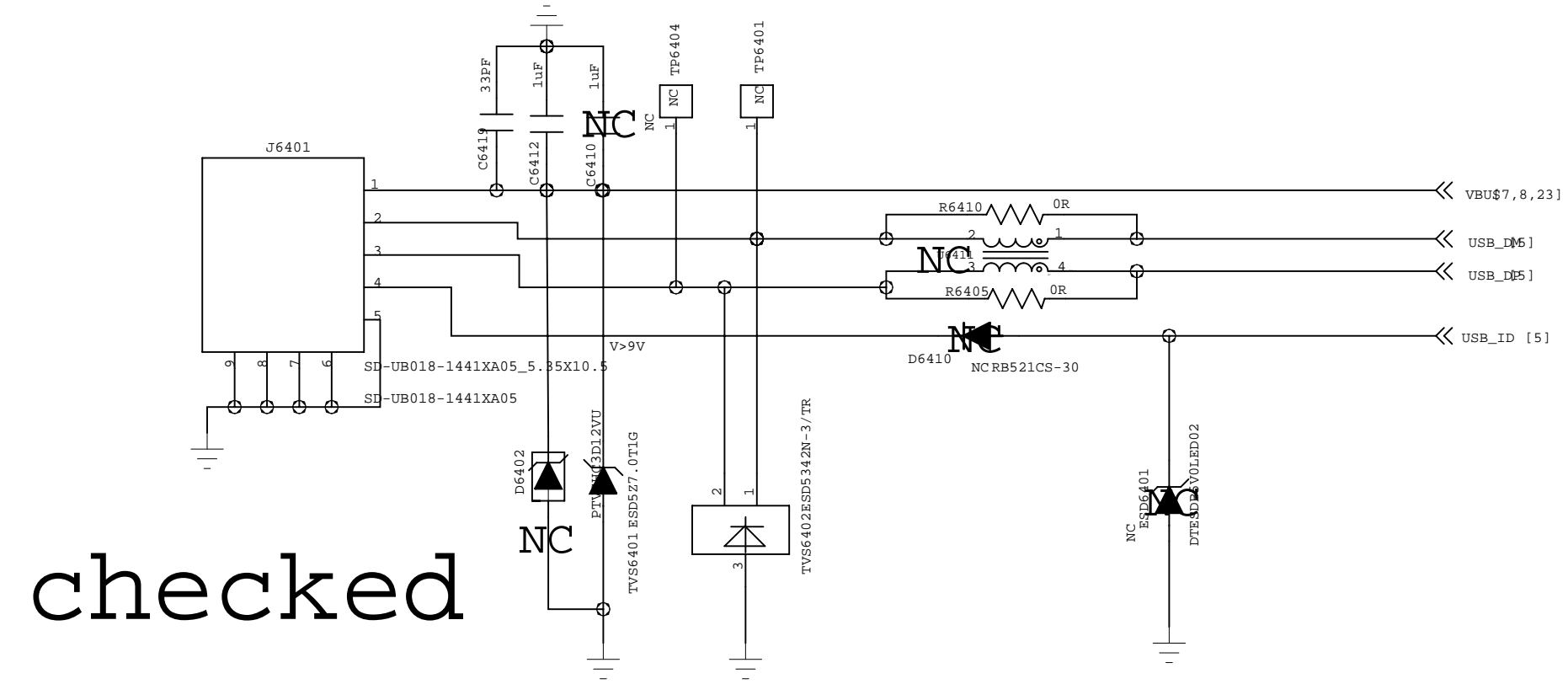
Default LIS3DHTR

SAR Sensor

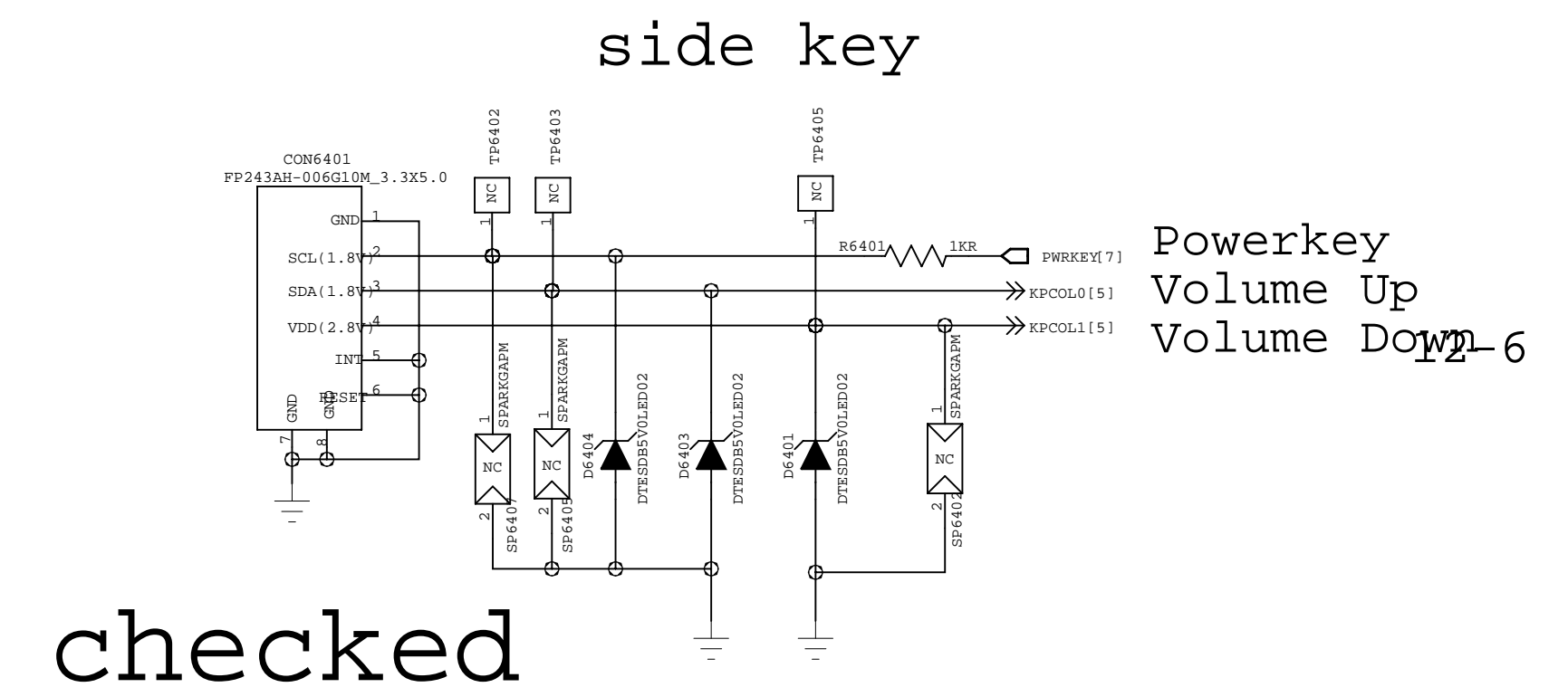


Thermistor / To sense board level temperature

have checked

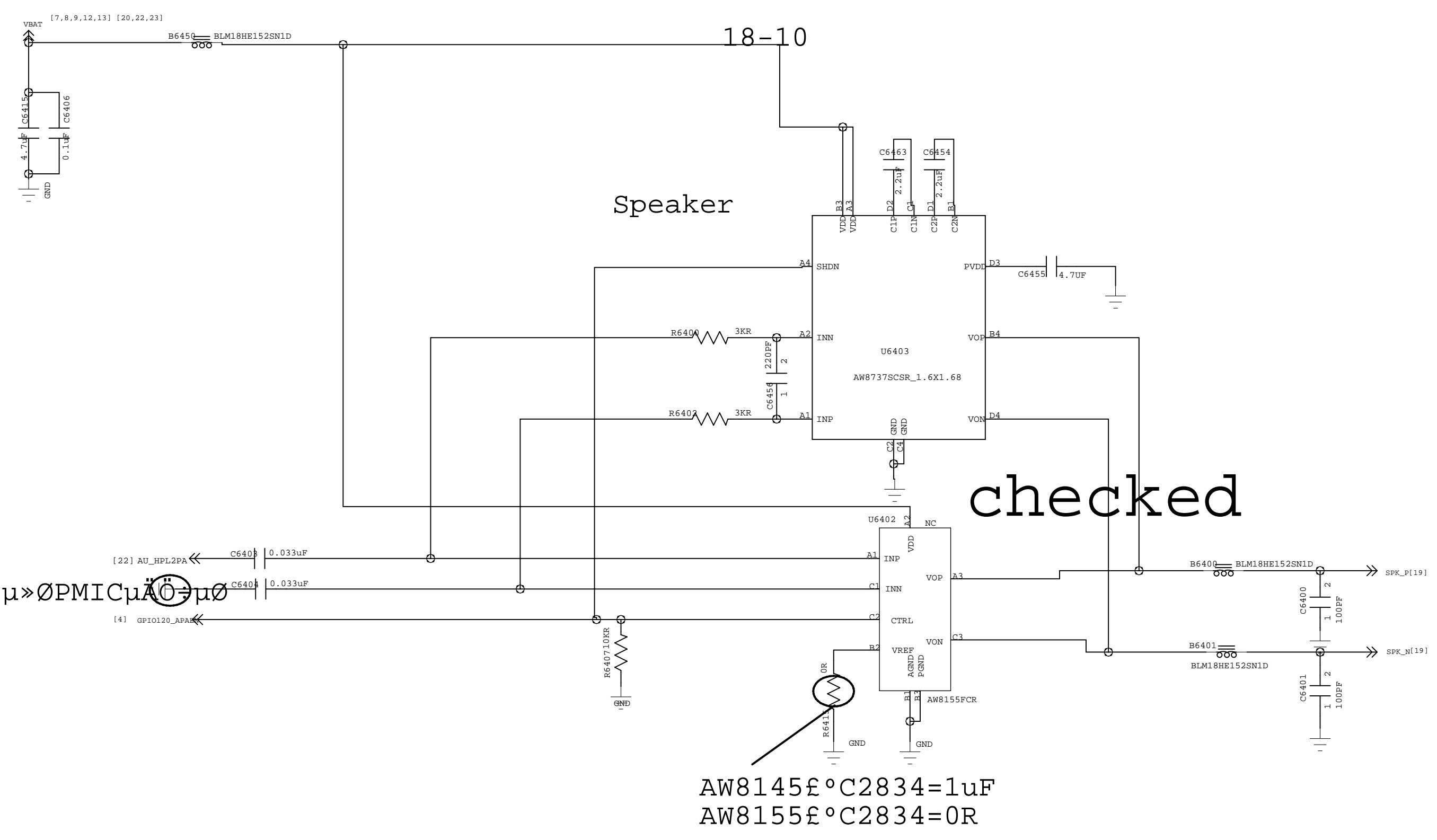


checked



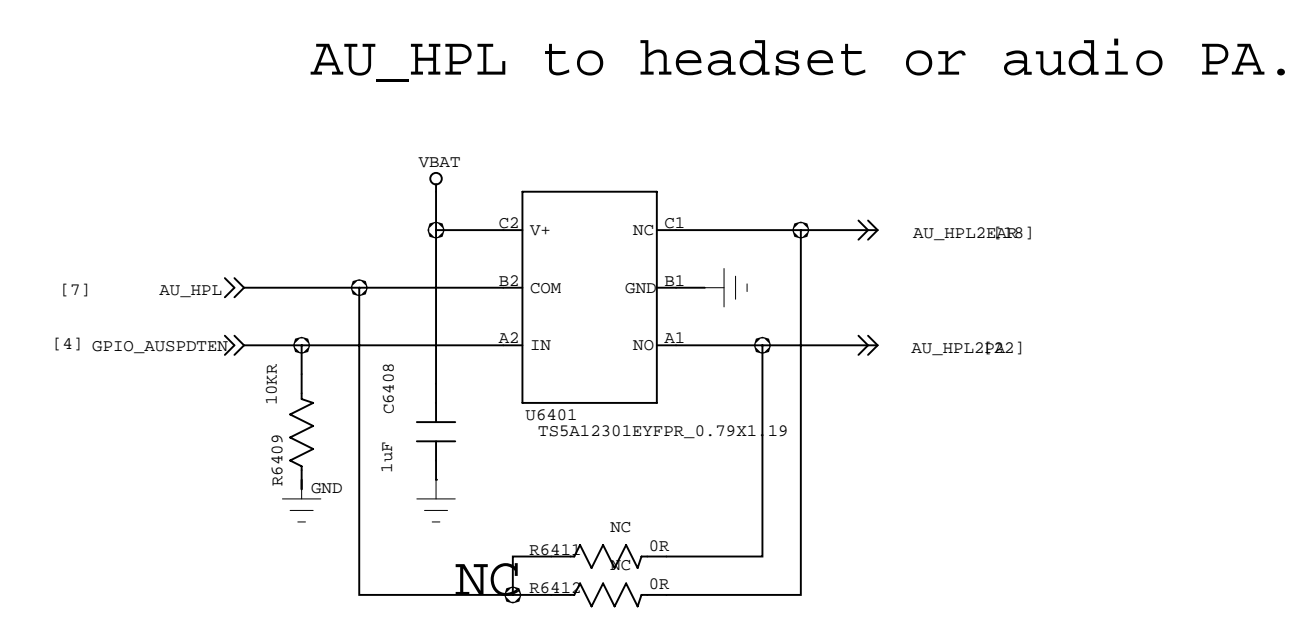
checked

Powerkey
Volume Up
Volume Down



checked

AW8145f°C2834=1uF
AW8155f°C2834=0R

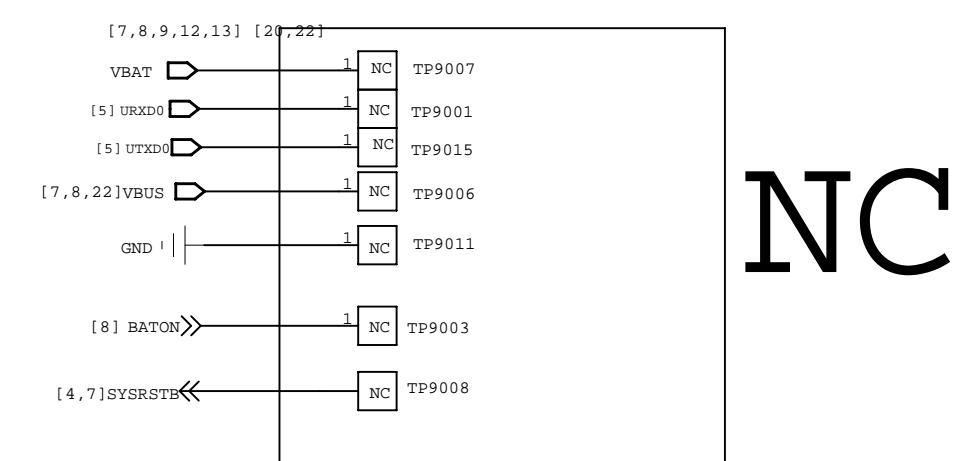


AU_HPL to headset or audio PA.

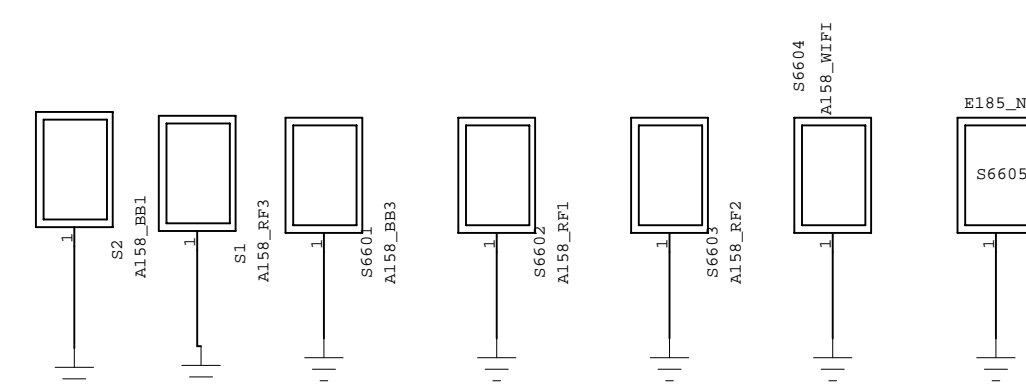
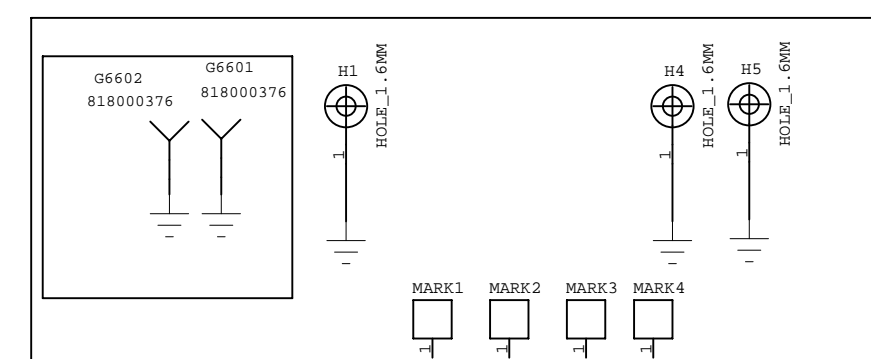
UART0 » ÊÇ² âÊÔ² » ° ´ ÕÕÉú² úÒª Çó

¿ª¹ Ø» ú¼üµçÔ´¼ü£¬USB°´ ÕÕÉú² úÒª Çó°Û·Å2.5mm

TEST POINTS



½ÓµØµ¬Æ¬, Ä818000376



have checked

Title		65_TEST POINT
Size	D Yude Confidential	
Data	Sep 14, 2016	Sheet 11 of 99

